80C186EC/80C188EC AND 80L186EC/80L188EC **16-BIT HIGH-INTEGRATION EMBEDDED PROCESSORS**

- Fully Static Operation
- True CMOS Inputs and Outputs
- Integrated Feature Set:
 - Low-Power, Static, Enhanced 8086 **CPU Core**
 - Two Independent DMA Supported UARTs, each with an Integral Baud **Rate Generator**
 - Four Independent DMA Channels
 - 22 Multiplexed I/O Port Pins
 - Two 8259A Compatible Programmable Interrupt Controllers
 - Three Programmable 16-Bit Timer/ Counters
 - 32-Bit Watchdog Timer
 - Ten Programmable Chip Selects with Integral Wait-State Generator
 - Memory Refresh Control Unit
 - Power Management Unit
 - On-Chip Oscillator
 - System Level Testing Support (ONCE Mode)
- Direct Addressing Capability to 1 Mbyte Memory and 64 Kbyte I/O
- Low-Power Operating Modes:
 - Idle Mode Freezes CPU Clocks but **Keeps Peripherals Active**
 - Powerdown Mode Freezes All Internal Clocks
 - Powersave Mode Divides All Clocks by Programmable Prescalar

- Available in Extended Temperature Range (-40° C to $+85^{\circ}$ C)
- Supports 80C187 Numerics Processor Extension (80C186EC only)
- Package Types:
 - 100-Pin EIAJ Quad Flat Pack (QFP)
 - 100-Pin Plastic Quad Flat Pack (PQFP)
 - 100-Pin Shrink Quad Flat Pack (SQFP)
- Speed Versions Available (5V):
 - 25 MHz (80C186EC25/80C188EC25)
 - 20 MHz (80C186EC20/80C188EC20)
 - 13 MHz (80C186EC13/80C188EC13)
- Speed Version Available (3V): - 16 MHz (80L186EC16/80L188EC16)
 - 13 MHz (80L186EC13/80L188EC13)

The 80C186EC is a member of the 186 Integrated Processor Family. The 186 Integrated Processor Family incorporates several different VLSI devices all of which share a common CPU architecture: the 8086/8088. The 80C186EC uses the latest high density CHMOS technology to integrate several of the most common system peripherals with an enhanced 8086 CPU core to create a powerful system on a single monolithic silicon die.

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80C186EC/80C188EC and 80L186EC/80L188EC 16-BIT HIGH-INTEGRATION EMBEDDED PROCESSOR

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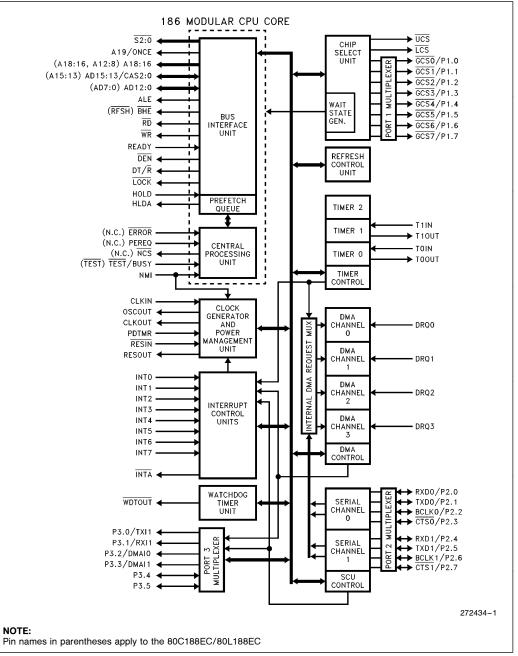


Figure 1. 80C186EC/80L186EC Block Diagram

INTRODUCTION

Unless specifically noted, all references to the 80C186EC apply to the 80C188EC, 80L186EC, and 80L188EC. References to pins that differ between the 80C186EC/80L186EC and the 80C188EC/80L188EC are given in parentheses. The "L" in the part number denotes low voltage operation. Physically and functionally, the "C" and "L" devices are identical.

The 80C186EC is one of the highest integration members of the 186 Integrated Processor Family. Two serial ports are provided for services such as interprocessor communication, diagnostics and modem interfacing. Four DMA channels allow for high speed data movement as well as support of the onboard serial ports. A flexible chip select unit simplifies memory and peripheral interfacing. The three general purpose timer/counters can be used for a variety of time measurement and waveform generation tasks. A watchdog timer is provided to insure system integrity even in the most hostile of environments. Two 8259A compatible interrupt controllers handle internal interrupts, and, up to 57 external interrupt requests. A DRAM refresh unit and 24 multiplexed I/O ports round out the feature set of the 80C186FC

The future set of the 80C186EC meets the needs of low-power, space-critical applications. Low-power applications benefit from the static design of the CPU and the integrated peripherals as well as low voltage operation. Minimum current consumption is achieved by providing a powerdown mode that halts operaton of the device and freezes the clock circuits. Peripheral design enhancements ensure that non-initialized peripherals consume little current.

The 80L186EC is the 3V version of the 80C186EC. The 80L186EC is functionally identical to the 80C186EC embedded processor. Current 80C186EC users can easily upgrade their designs to use the 80L186EC and benefit from the reduced power consumption inherent in 3V operation.

Figure 1 shows a block diagram of the 80C186EC/ 80C188EC. The execution unit (EU) is an enhanced 8086 CPU core that includes: dedicated hardware to speed up effective address calculations, enhanced execution speed for multiple-bit shift and rotate instructions and for multiple-bit shift and rotate instructions and for multiple and divide instructions, string move instructions that operate at full bus bandwidth, ten new instructions and fully static operation. The bus interface unit (BIU) is the same as that found on the original 186 family products, except the queue-status mode has been deleted and buffer interface control has been changed to ease system design timings. An independent internal bus is used for communication between the BIU and onchip peripherals.

80C186EC CORE ARCHITECTURE

Bus Interface Unit

The 80C186EC core incorporates a bus controller that generates local bus control signals. In addition, it employs a HOLD/HLDA protocol to share the local bus with other bus masters.

The bus controller is responsible for generating 20 bits of address, read and write strobes, bus cycle status information and data (for write operations) information. It is also responsible for reading data from the local bus during a read operation. A ready input pin is provided to extend a bus cycle beyond the minimum four states (clocks).

The bus controller also generates two control signals ($\overline{\text{DEN}}$ and $\text{DT}/\overline{\text{R}}$) when interfacing to external transceiver chips. This capability allows the addition of transceivers for simple buffering of the multiplexed address/data bus.

Clock Generator

The 80C186EC provides an on-chip clock generator for both internal and external clock generation. The clock generator features a crystal oscillator, a divideby-two counter and three low-power operating modes.

The oscillator circuit is designed to be used with either a parallel resonant fundamental or third-overtone mode crystal network. Alternatively, the oscillator circuit may be driven from an external clock source. Figure 2 shows the various operating modes of the oscillator circuit.

The crystal or clock frequency chosen must be twice the required processor operating frequency due to the internal divide-by-two counter. This counter is used to drive all internal phase clocks and the external CLKOUT signal. CLKOUT is a 50% duty cycle processor clock and can be used to drive other system components. All AC timings are referenced to CLKOUT.

The following parameters are recommended when choosing a crystal:

Temperature Range:	Application Specific
ESR (Equivalent Series Res.):	40Ω max
C0 (Shunt Capacitance of Crysta	al): 7.0 pF max
C _L (Load Capacitance):	20 pF \pm 2 pF
Drive Level:	1 mW (max)

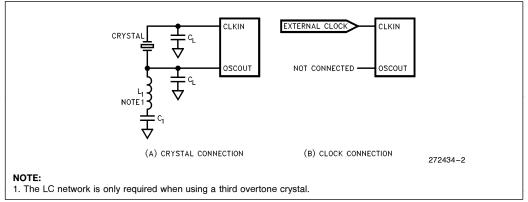


Figure 2. 80C186EC Clock Connections

80C186EC PERIPHERAL ARCHITECTURE

The 80C186EC integrates several common system peripherals with a CPU core to create a compact, yet powerful system. The integrated peripherals are designed to be flexbile and provide logical interconnections between supporting units (e.g., the DMA unit can accept requests from the Serial Communications Unit).

The list of integrated peripherals includes:

- Two cascaded, 8259A compatible, Programmable Interrupt Controllers
- 3-Channel Timer/Counter Unit
- 2-Channel Serial Communications Unit
- 4-Channel DMA Unit

- 10-Output Chip-Select Unit
- 32-bit Watchdog Timer Unit
- I/O Port Unit
- Refresh Control Unit
- Power Management Unit

The registers associated with each integrated peripheral are contained within a 128 x 16-bit register file called the Peripheral Control Block (PCB). The base address of the PCB is programmable and can be located on any 256 byte address boundary in either memory or I/O space.

Figure 3 provides a list of the registers associated with the PCB. The Register Bit Summary individually lists all of the registers and identifies each of their programming attributes.

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PCB Offset	Function			
00H	Master PIC Port 0			
02H	Master PIC Port 1			
04H	Slave PIC Port 0			
06H	Slave PIC Port 1			
08H	Reserved			
0AH	SCU Int. Req. Ltch			
0CH	DMA Int. Req. Ltch			
0EH	TCU Int. Req. Ltch			
10H	Reserved			
12H	Reserved			
14H	Reserved			
16H	Reserved			
18H	Reserved			
1AH	Reserved			
1CH	Reserved			
1EH	Reserved			
20H	WDT Reload High			
22H	WDT Reload Low			
24H	WDT Count High			
26H	WDT Count Low			
28H	WDT Clear			
2AH	WDT Disable			
2CH	Reserved			
2EH	Reserved			
30H	T0 Count			
32H	T0 Compare A			
34H	T0 Compare B			
46H	T0 Control			
38H	T1 Count			
3AH	T1 Compare A			
3CH	T1 Compare B			
3EH	T1 Control			

PCB Offset	Function	PCE Offse
40H	T2 Count	80H
42H	T2 Compare	82H
44H	Reserved	84
46H	T2 Control	86H
48H	Port 3 Direction	88H
4AH	Port 3 Pin State	8AH
4CH	Port 3 Mux Control	8CH
4EH	Port 3 Data Latch	8EH
50H	Port 1 Direction	90H
52H	Port 1 Pin State	92H
54H	Port 1 Mux Control	94
56H	Port 1 Data Latch	96H
58H	Port 2 Direction	98H
5AH	Port 2 Pin State	9AH
5CH	Port 2 Mux Control	9CH
5EH	Port 2 Data Latch	9EH
60H	SCU 0 Baud	AOH
62H	SCU 0 Count	A2H
64H	SCU 0 Control	A4H
66H	SCU 0 Status	A6H
68H	SCU 0 RBUF	A8H
6AH	SCU 0 TBUF	AAH
6CH	Reserved	ACH
6EH	Reserved	AEH
70H	SCU 1 Baud	BOH
72H	SCU 1 Count	B2H
74H	SCU 1 Control	B4H
76H	SCU 1 Status	B6H
78H	SCU 1 RBUF	B8H
7AH	SCU 1 TBUF	BAH
7CH	Reserved	BCH
7EH	Reserved	BEH

PCB Offset	Function					
80H	GCS0 Start					
82H	GCS0 Stop					
84H	GCS1 Start					
86H	GCS1 Stop					
88H	GCS2 Start					
8AH	GCS2 Stop					
8CH	GCS3 Start					
8EH	GCS3 Stop					
90H	GCS4 Start					
92H	GCS4 Stop					
94H	GCS5 Start					
96H	GCS5 Stop					
98H	GCS6 Start					
9AH	GCS6 Stop					
9CH	GCS7 Start					
9EH	GCS7 Stop					
A0H	LCS Start					
A2H	LCS Stop					
A4H	UCS Start					
A6H	UCS Stop					
A8H	Relocation Register					
AAH	Reserved					
ACH	Reserved					
AEH	Reserved					
B0H	Refresh Base Addr.					
B2H	Refresh Time					
B4H	Refresh Control					
B6H	Refresh Address					
B8H	Power Control					
BAH	Reserved					
BCH	Step ID					
BEH	Powersave					

PCB Offset	Function
C0H	DMA 0 Source Low
C2H	DMA 0 Source High
C4H	DMA 0 Dest. Low
C6H	DMA 0 Dest. High
C8H	DMA 0 Count
CAH	DMA 0 Control
ССН	DMA Module Pri.
CEH	DMA Halt
D0H	DMA 1 Source Low
D2H	DMA 1 Source High
D4H	DMA 1 Dest. Low
D6H	DMA 1 Dest. High
D8H	DMA 1 Count
DAH	DMA 1 Control
DCH	Reserved
DEH	Reserved
E0H	DMA 2 Source Low
E2H	DMA 2 Source High
E4H	DMA 2 Dest. Low
E6H	DMA 2 Dest. High
E8H	DMA 2 Count
EAH	DMA 2 Control
ECH	Reserved
EEH	Reserved
F0H	DMA 3 Source Low
F2H	DMA 3 Source High
F4H	DMA 3 Dest. Low
F6H	DMA 3 Dest. High
F8H	DMA 3 Count
FAH	DMA 3 Control
FCH	Reserved
FEH	Reserved

Figure 3. Peripheral Control Block Registers

Programmable Interrupt Controllers

The 80C186EC utilizes two 8259A compatible Programmable Interrupt Controllers (PIC) to manage both internal and external interrupts. The 8259A modules are configured in a master/slave arrangement.

Seven of the external interrupt pins, INT0 through INT6, are connected to the master 8259A module. The eighth external interrupt pin, INT7, is connected to the slave 8259A module.

There are a total of 11 internal interrupt sources from the integrated peripherals: 4 Serial, 4 DMA and 3 Timer/Counter.

Timer/Counter Unit

The 80C186EC Timer/Counter Unit (TCU) provides three 16-bit programmable timers. Two of these are highly flexible and are connected to external pins for external control or clocking. The third timer is not connected to any external pins and can only be clocked internally. However, it can be used to clock the other two timer channels. The TCU can be used to count external events, time external events, generate non-repetitive waveforms or generate timed interrupts.

Serial Communications Unit

The 80C186EC Serial Communications Unit (SCU) contains two independent channels. Each channel is identical in operation except that only channel 0 is directly supported by the integrated interrupt controller (the channel 1 interrupts are routed to external interrupt pins). Each channel has its own baud rate generator and can be internally or externally clocked up to one half the processor operating frequency. Both serial channels can request service from the DMA unit thus providing block reception and transmission without CPU intervention.

Independent baud rate generators are provided for each of the serial channels. For the asynchronous modes, the generator supplies an 8x baud clock to both the receive and transmit shifting register logic. A 1x baud clock is provided in the synchronous mode.

DMA Unit

The four channel Direct Memory Access (DMA) Unit is comprised of two modules with two channels each. All four channels are identical in operation. DMA transfers can take place from memory to memory, I/O to memory, memory to I/O or I/O to I/O. DMA requests can be external (on the DRQ pins), internal (from Timer 2 or a serial channel) or software initiated.

The DMA Unit transfers data as bytes only. Each data transfer requires at least two bus cycles, one to fetch data and one to deposit. The minimum clock count for each transfer is 8, but this will vary depending on synchronization and wait states.

Chip-Select Unit

The 80C186EC Chip-Select Unit (CSU) integrates logic which provides up to ten programmable chipselects to access both memories and peripherals. In addition, each chip-select can be programmed to automatically insert additional clocks (wait states) into the current bus cycle, and/or automatically terminate a bus cycle independent of the condition of the READY input pin.

I/O Port Unit

The I/O Port Unit on the 80C186EC supports two 8-bit channels and one 6-bit channel of input, output or input/output operation. Port 1 is multiplexed with the chip select pins and is output only. Port 2 is multiplexed with the pins for serial channels 1 and 2. All Port 2 pins are input/output. Port 3 has a total of 6 pins: four that are multiplexed with DMA and serial port interrupts and two that are non-multiplexed, open drain I/O.

Refresh Control Unit

The Refresh Control Unit (RCU) automatically generates a periodic memory read bus cycle to keep dynamic or pseudo-static memory refreshed. A 9-bit counter controls the number of clocks between refresh requests.

A 12-bit address generator is maintained by the RCU and is presented on the A12:1 address lines during the refresh bus cycle. Address bits A19:13 are programmable to allow the refresh address block to be located on any 8 Kbyte boundary.

Watchdog Timer Unit

The Watchdog Timer Unit (WDT) allows for graceful recovery from unexpected hardware and software upsets. The WDT consists of a 32-bit counter that decrements every clock cycle. If the counter reaches zero before being reset, the WDTOUT pin is

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pulled low for four clock cycles. Logically ANDing the WDTOUT pin with the power-on reset signal allows the WDT to reset the device in the event of a WDT timeout. If a less drastic method of recovery is desired. WDTOUT can be connected directly to NMI or one of the INT input pins. The WDT may also be used as a general purpose timer.

Power Management Unit

The 80C186EC Power Management Unit (PMU) is provided to control the power consumption of the device. The PMU provides four power management modes: Active, Powersave, Idle and Powerdown.

Active Mode indicates that all units on the 80C186EC are operating at $\frac{1}{2}$ the CLKIN frequency.

Idle Mode freezes the clocks of the Execution and Bus units at a logic zero state (all peripherals continue to operate normally).

The Powerdown Mode freezes all internal clocks at a logic zero level and disables the crystal oscillator.

In Powersave Mode, all internal clock signals are divided by a programmable prescalar (up to 1/64 the normal frequency). Powersave Mode can be used with Idle Mode as well as during normal (Active Mode) operation.

80C187 Interface (80C186EC only)

The 80C186EC supports the direct connection of the 80C187 Numerics Processor Extension. The 80C187 can dramatically improve the performance of calculation intensive applications.

ONCE Test Mode

To facilitate testing and inspection of devices when fixed into a target system, the 80C186EC has a test mode available which forces all output and input/ output pins to be placed in the high-impedance state. ONCE stands for "ON Circuit Emulation", The ONCE mode is selected by forcing the A19/S6/ONCE pin low during a processor reset (this pin is weakly held high during reset to prevent inadvertant entrance into ONCE Mode).

PACKAGE INFORMATION

This section describes the pin functions, pinout and thermal characteristics for the 80C186EC in the Plastic Quad Flat Pack (JEDEC PQFP), the EIAJ Quad Flat Pack (QFP) and the Shrink Quad Flat Pack (SQFP). For complete package specifications

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and information, see the Intel Packaging Outlines and Dimensions Guide (Order Number: 231369).

Prefix Identification

Table 1 lists the prefix identifications. **Table 1: Prefix Identification**

Prefix	Note	Package Type	Temperature Range
х		QFP (EIAJ)	Extended
х	1	PQFP	Extended/Commercial
х	1	SQFP	Extended/Commercial
x	1	QFP (EIAJ)	Commercial

NOTE:

- The 5V 25 MHz version is only available in commercial temperature range corresponding to 0°C to a 70°C ambient.
- To address the fact that many of the package prefix variables have changed, all package prefix variables in this document are now indicated with an "x".

Pin Descriptions

Each pin or logical set of pins is described in Table 2, There are four columns for each entry in the Pin Description Table. The following sections describe each column.

Column 1. Pin Name

In this column is a mnemonic that describes the pin function. Negation of the signal name (i.e. RESIN) implies that the signal is active low.

Column 2. Pin Type

A pin may be either power (P), ground (G), input only (I), output only (O) or input/output (I/O). Please note that some pins have more than 1 function. A19/S6/ONCE, for example, is normally an output but functions as an input during reset. For this reason A19/S6/ONCE is classified as an input/ output pin.

Column 3. Input Type (for I and I/O types only)

There are two different types of input pins on the 80C186EC: asynchronous and synchronous. **Asynchronous** pins require that setup and hold times be met only to *guarantee recognition*. **Synchronous** input pins require that the setup and hold times be met to *guarantee proper operation*. Stated simply, missing a setup or hold on an asynchronous pin will result in something minor (i.e. a timer count will be missed) whereas missing a setup or hold on a synchronous pin will result in system failure (the system will "lock up").

An input pin may also be edge or level sensitive.



Column 4: Output States (for O and I/O types only)

The state of an output or I/O pin is dependent on the operating mode of the device. There are four modes of operation that are different from normal active mode: Bus Hold, Reset, Idle Mode, Powerdown Mode. This column describes the output pin state in each of these modes.

The legend for interpreting the information in the Pin Descriptions is shown in Table 1.

As an example, please refer to the table entry for AD12:0. The "I/O" signifies that the pins are bidirectional (i.e. have both an input and output function). The "S" indicates that, as an input the signal must be synchronized to CLKOUT for proper operation. The "H(Z)" indicates that these pins will float while

the processor is in the Hold Acknowledge state. R(Z) indicates that these pins will float while \overline{RESIN} is low. P(0) and I(0) indicate that these pins will drive 0 when the device is in either Powerdown or Idle Mode.

Some pins, the I/O Ports for example, can be programmed to perform more than one function. Multifunction pins have a "/" in their signal name between the different functions (i.e. P3.0/RXI1). If the input pin type or output pin state differ between functions, then that will be indicated by separating the state (or type) with a "/" (i.e. H(X)/H(Q)). In this example when the pin is configured as P3.0 then its hold output state is H(X); when configured as RXI1 its output state is H(Q).

All pins float while the processor is in the ONCE Mode (with the exception of OSCOUT).

Symbol	Description
P	Power Pin (apply $+ V_{CC}$ voltage)
G	Ground (connect to V_{SS})
I	Input only pin
O	Output only pin
I/O	Input/Output pin
S(E)	Synchronous, edge sensitive
S(L)	Synchronous, level sensitive
A(E)	Asynchronous, edge sensitive
A(L)	Asynchronous, level sensitive
H(1)	Output driven to V_{CC} during bus hold
H(0)	Output driven to V_{SS} during bus hold
H(Z)	Output floats during bus hold
H(Q)	Output remains active during bus hold
H(X)	Output retains current state during bus hold
R(WH)	Output weakly held at V_{CC} during reset
R(1)	Output driven to V_{CC} during reset
R(0)	Output driven to V_{SS} during reset
R(Z)	Output floats during reset
R(Q)	Output remains active during reset
R(X)	Output retains current state during reset
l(1)	Output driven to V_{CC} during Idle Mode
l(0)	Output driven to V_{SS} during Idle Mode
l(Z)	Output floats during Idle Mode
l(Q)	Output remains active during Idle Mode
l(X)	Output retains current state during Idle Mode
P(1)	Output driven to V_{CC} during Powerdown Mode
P(0)	Output driven to V_{SS} during Powerdown Mode
P(Z)	Output floats during Powerdown Mode
P(Q)	Output remains active during Powerdown Mode
P(X)	Output retains current state during Powerdown Mode

Table 1. Pin Description Nomenclature

Pin Name	Pin Type	Input Type	Output States	Pin Description
V _{CC}	Р	_	_	POWER $+5V \pm 10\%$ power supply connection
V _{SS}	G	_	_	GROUND
CLKIN	I	A(E)	_	CLocK INput is the external clock input. An external oscillator operating at two times the required processor operating frequency can be connected to CLKIN. For crystal operation, CLKIN (along with OSCOUT) are the crystal connections to an internal Pierce oscillator.
OSCOUT	0		H(Q) R(Q) I(Q) P(X)	OSCillator OUTput is only used when using a crystal to generate the internal clock. OSCOUT (along with CLKIN) are the crystal connections to an internal Pierce oscillator. This pin can not be used as 2X clock output for non-crystal applications (i.e. this pin is not connected for non-crystal applications).
CLKOUT	0	_	H(Q) R(Q) I(Q) P(X)	CLock OUTput provides a timing reference for inputs and outputs of the processor, and is one-half the input clock (CLKIN) frequency. CLKOUT has a 50% duty cycle and transitions every falling edge of CLKIN.
RESIN	I	A(L)		RESet IN causes the processor to immediately terminate any bus cycle in progress and assume an initialized state. All pins will be driven to a known state, and RESOUT will also be driven active. The rising edge (low-to-high) transition synchronizes CLKOUT with CLKIN before the processor begins fetching opcodes at memory location 0FFF0H.
RESOUT	0	_	H(0) R(1) I(0) P(0)	RESet OUTput that indicates the processor is currently in the reset state. RESOUT will remain active as long as RESIN remains active.
PDTMR	1/0	A(L)	H(WH) R(Z) P(WH) I(WH)	Power-Down TiMeR pin (normally connected to an external capacitor) that determines the amount of time the processors waits after an exit from Powerdown before resuming normal operation. The duration of time required will depend on the startup characteristics of the crystal oscillator.
NMI	I	A(E)	—	Non-Maskable Interrupt input causes a TYPE-2 interrupt to be serviced by the CPU. NMI is latched internally.
TEST/BUSY (TEST)	I	A(E)		TEST is used during the execution of the WAIT instruction to suspend CPU operation until the pin is sampled active (LOW). TEST is alternately known as BUSY when interfacing with an 80C187 numerics coprocessor (80C186EC only).
A19/S6/ONCE	1/0	A(L)	H(Z) R(WH) I(0) P(0)	This pin drives address bit 19 during the address phase of the bus cycle. During T2 and T3 this pin functions as status bit 6. S6 is low to indicate CPU bus cycles and high to indicate DMA or refresh bus cycles. During a processor reset (RESIN active) this pin becomes the ONCE input pin. Holding this pin low during reset will force the part into ONCE Mode.

Table 2. Pin Descriptions

NOTE:



Table 2. Pin Descriptions (Continued)							
Pin Name	Pin Type	Input Type	Output States				Pin Description
A18/S5 A17/S4 A16/S3 (A15:8)	I/O	A(L)	H(Z) R(WH) I(0) P(0)	These pins drive address information during the address phase of the bus cycle. During T2 and T3 these pins drive status information (which is always 0 on the 80C186EC). These pins are used as inputs during factory test; driving these pins low during reset will cause unspecified operation. On the 80C188EC, A15:8 provide valid address information for the entire bus cycle.			
AD15/CAS2 AD14/CAS1 AD13/CAS0	1/0	S(L)	H(Z) R(Z) I(0) P(0)	These pins are part of the multiplexed ADDRESS and DATA bus. During the address phase of the bus cycle, address bits 15 through 13 are presented on these pins and can be latched using ALE. Data information is transferred during the data phase of the bus cycle. Pins AD15:13/CAS2:0 drive the 82C59 slave address information during interrupt acknowledge cycles.			
AD12:0 (AD7:0)	1/0	S(L)	H(Z) R(Z) I(0) P(0)	These pins provide a multiplexed ADDRESS and DATA bus. During the address phase of the bus cycle, address bits 0 through 12 (0 through 7 on the 80C188EC) are presented on the bus and can be latched using ALE. Data information is transferred during the data phase of the bus cycle.			
<u>S2:0</u>	0	_	H(Z) R(1) I(1)	R(1) transaction information. S2:0 are encoded as follows:			
			P(1)	S2	<u>S1</u>	SO	Bus Cycle Initiated
				0 0 0 1 1 1 1	0 0 1 1 0 0 1 1	0 1 0 1 0 1 0 1	Interrupt Acknowledge Read I/O Write I/O Processor HALT Instruction Queue Fetch Read Memory Write Memory Passive (No bus activity)
ALE	0		H(0) R(0) I(0) P(0)	Address Latch Enable output is used to strobe address information into a transparent type latch during the address phase of the bus cycle.			ansparent type latch during the address
BHE (RFSH)	0	_	H(Z) R(Z) I(1) P(1)	 Byte High Enable output to indicate that the bus cycle in progress is transferring data over the upper half of the data bus. BHE and A0 have the following logical encoding: 			
				A0	BHE		Encoding (for 80C186EC/ 80L186EC only)
							Word transfer Even Byte transfer Odd Byte transfer Refresh operation 80L188EC, RFSH is asserted low to
				Indic	ate a ref	resh b	us cycle.

Table 2. Pin Descriptions (Continued)

NOTE:

Table 2. Pin Descriptions (Continued)

Pin Name	Pin Type	Input Type	Output States	Pin Description
RD	0	_	H(Z) R(Z) I(1) P(1)	ReaD output signals that the accessed memory or I/O device should drive data information onto the data bus.
WR	0	_	H(Z) R(Z) I(1) P(1)	WRite output signals that data available on the data bus are to be written into the accessed memory or I/O device.
READY	I	A(L) S(L) (Note 1)		READY input to signal the completion of a bus cycle. READY must be active to terminate any 80C186EC bus cycle, unless it is ignored by correctly programming the Chip-Select unit.
DEN	0	_	H(Z) R(Z) I(1) P(1)	Data ENable output to control the enable of bi-directional transceivers in a buffered system. \overline{DEN} is active only when data is to be transferred on the bus.
DT/R	0	_	H(Z) R(Z) I(X) P(X)	Data Transmit/Receive output controls the direction of a bi- directional buffer in a buffered system.
LOCK	1/0	A(L)	H(Z) R(Z) I(X) P(X)	LOCK output indicates that the bus cycle in progress is not interruptable. The processor will not service other bus requests (such as HOLD) while LOCK is active. This pin is configured as a weakly held high input while RESIN is active and must not be driven low.
HOLD	I	A(L)	_	HOLD request input to signal that an external bus master wishes to gain control of the local bus. The processor will relinquish control of the local bus between instruction boundaries that are not LOCKed.
HLDA	0	—	H(1) R(0) I(0) P(0)	HoLD Acknowledge output to indicate that the processor has relinquished control of the local bus. When HLDA is asserted, the processor will (or has) floated its data bus and control signals allowing another bus master to drive the signals directly.
NCS	0		H(1) R(1) I(1) P(1)	Numerics Coprocessor Select output is generated when acessing a numerics coprocessor. This signal does not exist on the 80C188EC/80L188EC.
ERROR		A(L)	_	ERROR input that indicates the last numerics processor extension operation resulted in an exception condition. An interrupt TYPE 16 is generated if ERROR is sampled active at the beginning of a numerics operation. Systems not using an 80C187 must tie ERROR to V_{CC} . This signal does not exist on the 80C188EC/80L188EC.

NOTE:

Pin Name	Pin Type	Input Type	Output States	Pin Description
PEREQ	Ι	A(L)	_	Processor Extension REQuest signals that a data transfer between an 80C187 Numerics Processor Extension and Memory is pending. Systems not using an 80C187 must tie this pin to V_{SS} . This signal does not exist on the 80C188EC/80L188EC.
UCS	0	_	H(1) R(1) I(1) P(1)	Upper Chip Select will go active whenever the address of a memory or I/O bus cycle is within the address range programmed by the user. After reset, UCS is configured to be active for memory accesses between 0FFC00H and 0FFFFFH.
LCS	0		H(1) R(1) I(1) P(1)	Lower Chip Select will go active whenever the address of a memory or I/O bus cycle is within the address range programmed by the user. $\overrightarrow{\text{LCS}}$ is inactive after a reset.
P1.0/GCS0 P1.1/GCS1 P1.2/GCS2 P1.3/GCS3 P1.4/GCS4 P1.5/GCS5 P1.6/GCS6 P1.7/GCS7	Ο		H(X)/H(1) R(1) I(X)/I(1) P(X)/P(1)	These pins provide a multiplexed function. If enabled, each pin can provide a General purpose Chip Select output which will go active whenever the address of a memory or I/O bus cycle is within the address limitations programmed by the user. When not programmed as a Chip-Select, each pin may be used as a general purpose output port.
T0OUT T1OUT	0	_	H(Q) R(1) I(Q) P(X)	Timer OUTput pins can be programmed to provide single clock or continuous waveform generation, depending on the timer mode selected.
TOIN T1IN	I	A(L) A(E)	_	Timer INput is used either as clock or control signals, depending on the timer mode selected. This pin may be either level or edge sensitive depending on the programming mode.
INT7:0	I	A(L) A(E)	_	Maskable INTerrupt input will cause a vector to a specific Type interrupt routine. The INT6:0 pins can be used as cascade inputs from slave 8259A devices. The INT pins can be configured as level or edge sensitive.
ĪNTA	0	_	H(1) R(1) I(1) P(1)	INTerrupt Acknowledge output is a handshaking signal used by external 82C59A Programmable Interrupt Controllers.
P3.5 P3.4	1/0	A(L)	H(X) R(Z) I(X) H(X)	Bidirectional, open-drain port pins.
P3.3/DMAI1 P3.2/DMAI0	0		H(X) R(0) I(Q) P(X)	DMA Interrupt output goes active to indicate that the channel has completed a transfer. DMAI1 and DMAI0 are multiplexed with output only port functions.

Table 2. Pin Descriptions (Continued)

NOTE:

Pin Name	Pin Type	Input Type	Output States	Pin Description
P3.1/TXI1	0	_	H(X)/H(Q) R(0) I(Q) P(X)	Transmit Interrupt output goes active to indicate that serial channel 1 has completed a transfer. TXI1 is multiplexed with an output only Port function.
P3.0/RXI1	0		H(X)/H(Q) R(0) I(Q) P(X)	Receive Interrupt output goes active to indicate that serial channel 1 has completed a reception. RXI1 is multiplexed with an output only port function.
WDTOUT	0		H(Q) R(1) I(Q) P(X)	WatchDog Timer OUTput is driven low for four clock cycles when the watchdog timer reaches zero. WDTOUT may be ANDed with the power-on reset signal to reset the processor when the watchdog timer is not properly reset.
P2.7/CTS1 P2.3/CTS0	1/0	A(L)	H(X) R(Z) I(X) P(X)	Clear-To-Send input is used to prevent the transmission of serial data on the TXD signal pin. CTS1 and CTS0 are multiplexed with an I/O Port function.
P2.6/BCLK1 P2.2/BCLK0	1/0	A(L)/ A(E)	H(X) R(Z) I(X) P(X)	Baud CLocK input can be used as an alternate clock source for each of the integrated serial channels. The BCLK inputs are multiplexed with I/O Port functions. The BCLK input frequency cannot exceed $1/_2$ the operating frequency of the processor.
P2.5/TXD1 P2.1/TXD0	I/O	A(L)	H(Q) R(Z) I(X)/I(Q) P(X)	Transmit Data output provides serial data information. The TXD outputs are multiplexed with I/O Port functions. During synchronous serial communications, TXD will function as a clock output.
P2.4/RXD1 P2.0/RXD0	1/0	A(L)	H(X)/H(Q) R(Z) I(X)/I(Q) P(X)	Receive Data input accepts serial data information. The RXD pins are multiplexed with I/O Port functions. During synchronous serial communications, RXD is bi-directional and will become an output for transmission of data (TXD becomes the clock).
DRQ3:0	I	A(L)	_	DMA ReQuest input pins are used to request a DMA transfer. The timing of the request is dependent on the programmed synchronization mode.

Table 2. Pin Descriptions (Continued)

NOTES:

1. READY is A(E) for the rising edge of CLKOUT, S(E) for the falling edge of CLKOUT.



Pinout

Tables 3 and 4 list the pin names with package location for the 100-pin Plastic Quad Flat Pack (PQFP) component. Figure 4 depicts the PQFP package as viewed from the top side of the component (i.e. contacts facing down).

Tables 5 and 6 list the pin names with package location for the 100-pin EIAJ Quad Flat Pack (QFP) component. Figure 5 depicts the QFP package as viewed from the top side of the component (i.e. contacts facing down).

Tables 7 and 8 list the pin names with package location for the 100-pin Shrink Quad Flat Pack (SQFP) component. Figure 6 depicts the SQFP package as viewed from the top side of the component (i.e., contacts facing down).

AD Bus		Bus Cont	rol] [Processor Cor	ntrol	I/0		
Name	Pin	Name	Pin		Name	Pin	Name	Pin	
AD0	73	ALE	52] [RESIN	8	UCS	88	
AD1	72	BHE (RFSH)	51		RESOUT	7	LCS	89	
AD2	71	SO	78		CLKIN	10			
AD3	70	<u>S1</u>	79		OSCOUT	11	P1.7/GCS7	90	
AD4	66	S2	80		CLKOUT	6	P1.6/GCS6	91	
AD5	65	RD	50		TEST/BUSY	83	P1.5/GCS5	92	
AD6	64	WR	49		(TEST)		P1.4/GCS4	93	
AD7	63	READY	85		PEREQ (V _{SS})	81	P1.3/GCS3	94	
AD8 (A8)	60	DEN	47		NCS (N.C.)	35	P1.2/GCS2	95	
AD9 (A9)	59	DT/R	46		ERROR (V _{CC})	84	P1.1/GCS1	96	
AD10 (A10)	58	LOCK	48		PDTMR	9	P1.0/GCS0	97	
AD11 (A11)	57	HOLD	44		NMI	82			
AD12 (A12)	56	HLDA	45		INT0	30	P2.7/CTS1	23	
AD13/CAS0	55	INTA	34		INT1	31	P2.6/BCLK1	22	
(A13/CAS0)				1	INT2	32	P2.5/TXD1	21	
AD14/CAS1	54			ו ו	INT3	33	P2.4/RXD1	20	
(A14/CAS1)		Power and G	round		INT4	40	P2.3/CTS0	19	
AD15/CAS2	53	Name	Pin		INT5	41	P2.2/BCLK0	18	
(A15/CAS2)		V _{CC}	13	1	INT6	42	P2.1/TXD0	17	
A16/S3	77	Vcc	14		INT7	43	P2.0/RXD0	16	
A17/S4	76	V _{CC}	38	'					
A18/S5	75	Vcc	62				P3.5	29	
A19/S6/ONCE	74	V _{CC}	67				P3.4	28	
		Vcc	69				P3.3/DMAI1	27	
		V _{CC}	86				P3.2/DMAI0	26	
		V _{SS}	12				P3.1/TXI1	25	
		VSS	15				P3.0/RXI1	24	
		V _{SS}	37						
		V _{SS}	39				TOIN	3	
		V _{SS}	61				TOOUT	2	
		V _{SS}	68				T1IN	5	
		VSS	87				T1OUT	4	
		I		-			DRQ0	98	
							DRQ1	99	
							DRQ2	100	
							DRQ3	1	

Table 3. PQFP Pin Functions with Location

36

WDTOUT

80C186EC/188EC, 80L186EC/188EC

intel

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Pin	Name	Pin	Name	Pir	Name	Pin	Name
1	DRQ3	26	DMAI0/P3.2	51	BHE (RFSH)	76	A17/S4
2	TOOUT	27	DMAI1/P3.3	52	ALE	77	A16/S3
3	TOIN	28	P3.4	53	AD15 (A15)	78	SO
4	T1OUT	29	P3.5	54	AD14 (A14)	79	<u>S1</u>
5	T1IN	30	INT0	55	AD13 (A13)	80	S2
6	CLKOUT	31	INT1	56	AD12 (A12)	81	PEREQ (V _{SS})
7	RESOUT	32	INT2	57	AD11 (A11)	82	NMI
8	RESIN	33	INT3	58	AD10 (A10)	83	TEST
9	PDTMR	34	INTA	59	AD9 (A9)	84	ERROR (V _{CC})
10	CLKIN	35	NCS (N.C.)	60	AD8 (A8)	85	READY
11	OSCOUT	36	WDTOUT	61	V _{SS}	86	V _{CC}
12	V _{SS}	37	V _{SS}	62	V _{CC}	87	V _{SS}
13	V _{CC}	38	V _{CC}	63	AD7	88	UCS
14	V _{CC}	39	V _{SS}	64	AD6	89	LCS
15	V _{SS}	40	INT4	65	AD5	90	P1.7/GCS7
16	P2.0/RXD0	41	INT5	66	AD4	91	P1.6/GCS6
17	P2.1/TXD0	42	INT6	67	V _{CC}	92	P1.5/GCS5
18	P2.2/BCLK0	43	INT7	68	V _{SS}	93	P1.4/GCS4
19	P2.3/CTS0	44	HOLD	69	V _{CC}	94	P1.3/GCS3
20	P2.4/RXD1	45	HLDA	70	AD3	95	P1.2/GCS2
21	P2.5/TXD1	46	DT/R	71	AD2	96	P1.1/GCS1
22	P2.6/BCLK1	47	DEN	72	AD1	97	P1.0/GCS0
23	P2.7/CTS1	48	LOCK	73	AD0	98	DRQ0
24	P3.0/RXI1	49	WR	74	A19/S6/ONCE	99	DRQ1
25	P3.1/TXI1	50	RD	75	A18/S5	100	DRQ2

Table 4. PQFP Pin Locations with Pin Name

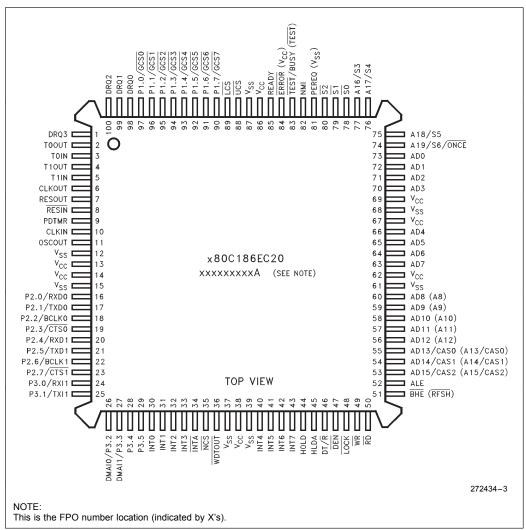


Figure 4. 100-Pin Plastic Quad Flat Pack Package (PQFP)

80C186EC/188EC, 80L186EC/188EC

intel

AD Bus		Bu
Name	Pin	Nar
AD0	76	ALE
AD1	75	BHE (F
AD2	74	<u>S0</u>
AD3	73	S1
AD4	69	S2
AD5	68	RD
AD6	67	WR
AD7	66	READ
AD8 (A8)	63	DEN
AD9 (A9)	62	DT/R
AD10 (A10)	61	LOCK
AD11 (A11)	60	HOLD
AD12 (A12)	59	HLDA
AD13/CAS0	58	INTA
(A13/CAS0)		
AD14/CAS1	57	Powe
(A14/CAS1)		
AD15/CAS2	56	Nam
(A15/CAS2)		V _{CC}
A16/S3	80	V _{CC}
A17/S4	79	V _{CC}
A18/S5	78	V _{CC}
A19/S6/ONCE	77	V _{CC}
		V _{CC}
		V _{CC}
		VSS

Table 5. QFP Pin Names with Pack	age Location
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Pin

-		•	
Bus Co	ntrol	Processor Co	ntrol
Name	Pin	Name	Pin
ALE BHE (RFSH S0 S1 S2 RD WR READY DEN DT/R LOCK HOLD HLDA INTA) 55 81 82 83 53 52 88 50 49 51 47 48 37	RESIN RESOUT CLKIN OSCOUT CLKOUT TEST/BUSY (TEST) PEREQ (V _{SS}) NCS (N.C.) ERROR (V _{CC}) PDTMR NMI INT0 INT1	11 10 13 14 9 86 84 38 87 12 85 33 34
		INT2 INT3	35
Power and	Ground	INT4	43
Name	Pin	INT5	44
V _{CC} V _{CC} V _{CC} V _{CC} V _{CC} V _{SS} V _{SS} V _{SS} V _{SS} V _{SS} V _{SS} V _{SS} V _{SS}	16 17 41 65 70 72 89 15 18 40 42 64 71 90	INT6 INT7	45 46

I/O							
Name	Pin						
UCS	91						
LCS	92						
P1.7/GCS7	93						
P1.6/GCS6	94						
P1.5/GCS5	95						
P1.4/GCS4	96						
P1.3/GCS3	97						
P1.2/GCS2	98						
P1.1/GCS1	99						
P1.0/GCS0	100						
P2.7/CTS1	26						
P2.6/BCLK1	25						
P2.5/TXD1	24						
P2.4/RXD1	23						
P2.3/CTS0	22						
P2.2/BCLK0	21						
P2.1/TXD0	20						
P2.0/RXD0	19						
P3.5	32						
P3.4	31						
P3.3/DMAI1	30						
P3.2/DMAI0	29						
P3.1/TXI1	28						
P3.0/RXI1	27						
TOIN	6						
TOOUT	5						
T1IN	8						
T1OUT	7						
DRQ0	1						
DRQ1	2						
DRQ2	3						
DRQ3	4						
WDTOUT	39						

3 DRQ2 28 P3.1/TXI1 53 RD 78 4 DRQ3 29 DMAI0/P3.2 54 BHE (RFSH) 79 5 TOOUT 30 DMAI0/P3.2 55 ALE 80 6 T0IN 31 P3.4 56 AD15 (A15) 81 7 T1OUT 32 P3.5 57 AD14 (A14) 82 8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER	AD0 /S6/ONCE A18/S5 A17/S4 A16/S3
2 DRQ1 27 P3.0/RXI1 52 WR 77 A19 3 DRQ2 28 P3.1/TXI1 53 RD 78 79 4 DRQ3 29 DMAI0/P3.2 54 BHE (RFSH) 79 79 5 TOOUT 30 DMAI1/P3.3 55 ALE 80 80 6 T0IN 31 P3.4 56 AD15 (A15) 81 81 7 T1OUT 32 P3.5 57 AD14 (A14) 82 83 9 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 8 11 RESIN 36 INT3 61 AD10 (A10) 86 88 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 <th>/S6/ONCE A18/S5 A17/S4 A16/S3</th>	/S6/ONCE A18/S5 A17/S4 A16/S3
3 DRQ2 28 P3.1/TXI1 53 RD 78 4 DRQ3 29 DMAI0/P3.2 54 BHE (RFSH) 79 5 TOOUT 30 DMAI0/P3.2 54 BHE (RFSH) 79 6 T0IN 31 P3.4 56 AD15 (A15) 81 7 T1OUT 32 P3.5 57 AD14 (A14) 82 8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 6	A18/S5 A17/S4 A16/S3
4 DRQ3 29 DMAI0/P3.2 54 BHE (RFSH) 79 5 TOOUT 30 DMAI1/P3.3 55 ALE 80 6 TOIN 31 P3.4 56 AD15 (A15) 81 7 T1OUT 32 P3.5 57 AD14 (A14) 82 8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 88 14 OSCOUT 39 WDTOUT 64 VSS 89 91 15 VSS 40 VSS 65 V _{CC} 90 91 16 V _{CC} 41	A17/S4 A16/S3
5 TOOUT 30 DMAI1/P3.3 55 ALE 80 6 TOIN 31 P3.4 56 AD15 (A15) 81 7 T1OUT 32 P3.5 57 AD14 (A14) 82 8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 VSS 89 15 VSS 40 VSS 65 V _{CC} 90 16 V _{CC} 41 V _{CC} 66 A	A16/S3
6 TOIN 31 P3.4 56 AD15 (A15) 81 7 T1OUT 32 P3.5 57 AD14 (A14) 82 8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 VSS 89 15 VSS 40 VSS 65 V _{CC} 90 16 V _{CC} 41 V _{CC} 66 AD7 91	
7 T1OUT 32 P3.5 57 AD14 (A14) 82 8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 V _{SS} 89 15 V _{SS} 40 V _{SS} 65 V _{CC} 90 16 V _{CC} 41 V _{CC} 66 AD7 91	
8 T1IN 33 INTO 58 AD13 (A13) 83 9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 VSS 89 15 VSS 40 VSS 65 V _{CC} 90 16 V _{CC} 41 V _{CC} 66 AD7 91	<u>S0</u>
9 CLKOUT 34 INT1 59 AD12 (A12) 84 PE 10 RESOUT 35 INT2 60 AD11 (A11) 85 11 11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 V _{SS} 89 15 V _{SS} 40 V _{SS} 65 V _{CC} 90 16 V _{CC} 41 V _{CC} 66 AD7 91	<u>S1</u>
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	S2
11 RESIN 36 INT3 61 AD10 (A10) 86 12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 VSS 89 15 VSS 40 VSS 65 V _{CC} 90 16 V _{CC} 41 V _{CC} 66 AD7 91	REQ (V _{SS})
12 PDTMR 37 INTA 62 AD9 (A9) 87 ER 13 CLKIN 38 NCS (N.C.) 63 AD8 (A8) 88 14 OSCOUT 39 WDTOUT 64 VSS 89 15 VSS 40 VSS 65 VCC 90 16 V _{CC} 41 V _{CC} 66 AD7 91	NMI
	TEST
	ROR (V _{CC})
	READY
	V _{CC}
	V _{SS}
17 V _{CC} 42 V _{SS} 67 AD6 92	UCS
	LCS
18 V _{SS} 43 INT4 68 AD5 93 P ⁻	.7/GCS7
19 P2.0/RXD0 44 INT5 69 AD4 94 P	.6/GCS6
20 P2.1/TXD0 45 INT6 70 V _{CC} 95 P ⁻	.5/GCS5
21 P2.2/BCLK0 46 INT7 71 V _{SS} 96 P ⁻	.4/GCS4
22 P2.3/CTS0 47 HOLD 72 V _{CC} 97 P ⁻	
	.3/GCS3
24 P2.5/TXD1 49 DT/R 74 AD2 99 P	.3/ <u>GCS3</u> .2/ <u>GCS2</u>
25 P2.6/BCLK1 50 DEN 75 AD1 100 P	

Table 6. QFP Package Location with Pin Names

80C186EC/188EC, 80L186EC/188EC

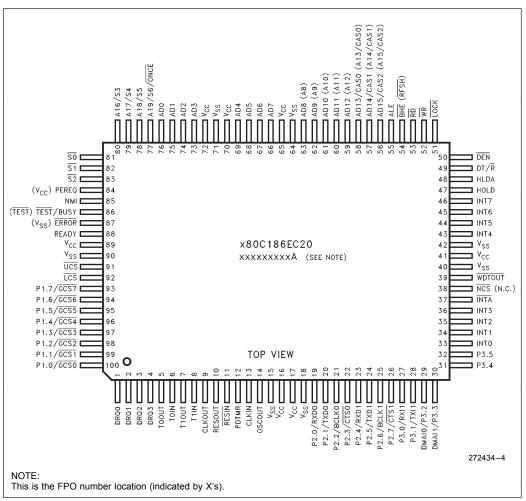


Figure 5: Quad Flat Pack (EIAJ) Pinout Diagram

intel

AD Bus							
AD0	73						
AD1	72						
AD2	71						
AD3	70						
AD4	66						
AD5	65						
AD6	64						
AD7	63						
AD8 (A8)	60						
AD9 (A9)	59						
AD10 (A10)	58						
AD11 (A11)	57						
AD12 (A12)	56						
AD13 (A13)	55						
AD14 (A14)	54						
AD15 (A15)	53						
A16	77						
A17	76						
A18	75						
A19/ONCE	74						

Table 7. SQFP Pin Functions with Location

52

51

78

79

80

50

49

85

46

47

48

44 45

Bus Control

ALE

S0

<u>S1</u>

 $\overline{S2}$

 $\overline{\mathsf{RD}}$

WR

READY

DT/R

DEN

LOCK

HOLD

HLDA

BHE (RFSH)

Processor Control				I/O	
RESIN		8		UCS	88
RESOUT		7		LCS	89
CLKIN		10			
OSCOUT		11		P1.0/GCS0	97
CLKOUT		6		P1.1/GCS1	96
TEST/BUS	Y	83		P1.2/GCS2	95
NMI		82		P1.3/GCS3	94
INT0		30		P1.4/GCS4	93
INT1		31		P1.5/GCS5	92
INT2 INT3		32 33		P1.6/GCS6 P1.7/GCS7	91 90
INT3 INT4		33 40		P1.//GC5/	90
INT5		40		P2.0/RXD0	16
INT6		42		P2.1/TXD0	17
INT7		43		P2.2/BCLK0	18
INTA		34		P2.3/CTS0	19
PEREQ (Vs	ss)	81		P2.4/RXD1	20
ERROR (V	,o, ,c)	84		P2.5/TXD1	21
NCS (N.C.)		35		P2.6/BCLK1	22
PDTMR		9		P2.7/CTS1	23
				P3.0/RXI1	24
Power and	d Gro	und		P3.1/TXI1	24
V _{CC}		13		P3.2/DMAI0	26
V _{CC}		14		P3.3/DMAI1	27
V _{CC}		38		P3.4	28
V _{CC}		62		P3.5	29
V _{CC}		67			
V _{CC}		69		DRQ0	98
		86		DRQ1	99
V _{SS}		12		DRQ2	100
V _{SS}		15		DRQ3	1
00		37		TOIN	
00		39		TOIN	3
V _{SS}		61		T0OUT T1IN	2
V _{SS}		68		T10UT	4
V _{SS}		87	ļ	WDTOUT	36
					- 30

Pin	Name	Pin	Name	Pin	Name	Pin	Name
1	DRQ3	26	P3.2/DMAI0	51	BHE (RFSH)	76	A17
2	TOOUT	27	P3.3/DMAI1	52	ALE	77	A16
3	TOIN	28	P3.4	53	AD15 (A15)	78	S 0
4	T1OUT	29	P3.5	54	AD14 (A14)	79	<u>S1</u>
5	T1IN	30	INT0	55	AD13 (A13)	80	S2
6	CLKOUT	31	INT1	56	AD12 (A12)	81	PEREQ (V _{SS})
7	RESOUT	32	INT2	57	AD11 (A11)	82	MNI
8	RESIN	33	INT3	58	AD10 (A10)	83	TEST/BUSY
9	PDTMR	34	INTA	59	AD9 (A9)		(TEST)
10	CLKIN	35	NSC (N.C.)	60	AD8 (A8)	84	ERROR (V _{CC})
11	OSCOUT	36	WDTOUT	61	V _{SS}	85	READY
12	V _{SS}	37	V _{SS}	62	V _{CC}	86 87	V _{CC}
13	V _{CC}	38	V _{CC}	63	AD7 (A7)	88	V _{SS} UCS
14	V _{CC}	39	V _{SS}	64	AD6 (A6)	89	
15	V _{SS}	40	INT4	65	AD5	90	P1.7/GCS7
16	P2.0/RXD0	41	INT5	66	AD4	91	P1.6/GS6
17	P2.1/TXD0	42	INT6	67	V _{CC}	92	P1.5/GCS5
18	P2.2/BCLK0	43	INT7	68	V _{SS}	93	P1.4/GCS4
19	P2.3/CTS0	44	HOLD	69	V _{CC}	94	P1.3/GCS3
20	P2.4/RXD1	45	HLDA	70	AD3	95	P1.2/GCS2
21	P2.5/TXD1	46	DT/R	71	AD2	96	P1.1/GCS1
22	P2.6/BCLK1	47	DEN	72	AD1	97	P1.0/GCS0
23	P2.7/CTS1	48	LOCK	73	AD0	98	DRQ0
24	P3.0/RXI1	49	WR	74	A19/ONCE	99	DRQ1
25	P3.1/TXI1	50	RD	75	AD18	100	DRQ2

Table 8. SQFP Pin Locations with Pin Names

80C186EC/188EC, 80L186EC/188EC

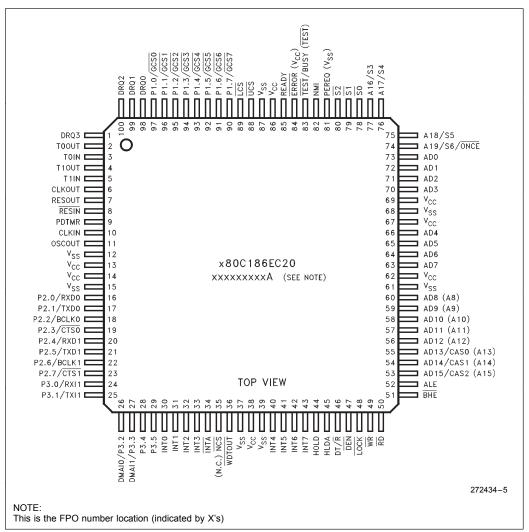


Figure 6: 100-Pin Shrink Quad Flat Pack Package (SQFP)

Package Thermal Specifications

The 80C186EC/80L186EC is specified for operation when T_C (the case temperature) is within the range of -40°C to $+100^\circ\text{C}$. T_C may be measured in any environment to determine whether the processor is within the specified operating range. The case temperature must be measured at the center of the top surface.

 T_A (the ambient temperature) can be calculated from θ_{CA} (thermal resistance from the case to ambient) with the following equation:

$$\mathsf{T}_{\mathsf{A}} = \mathsf{T}_{\mathsf{C}} - \mathsf{P} * \theta_{\mathsf{C}\mathsf{A}}$$

Typical values for θ_{CA} at various airflows are given in Table 9. P (the maximum power consumption specified in Watts) is calculated by using the maximum I_{CC} and V_{CC} of 5.5V.

	Airflow in ft/min (m/sec)						
	0 (0)	200 (1.01)	400 (2.03)	600 (3.04)	800 (4.06)	1000 (5.07)	
θ_{CA} (PQFP)	27.0	22.0	18.0	15.0	14.0	13.5	
θ_{CA} (QFP)	64.5	55.5	51.0	TBD	TBD	TBD	
θ_{CA} (SQFP)	62.0	TBD	TBD	TBD	TBD	TBD	

Table 9. Thermal Resistance (θ_{CA}) at Various Airflows (in °C/Watt)

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

Storage Temperature $\dots -65^{\circ}C$ to $+150^{\circ}C$
Case Temperature Under Bias -65° C to $+100^{\circ}$ C
Supply Voltage with Respect to V_{SS} $\ldots \ldots -0.5V$ to $+6.5V$
Voltage on Other Pins with Respect to V_{SS} $\ldots \ldots -0.5V$ to V_{CC} + 0.5V

NOTICE: This data sheet contains preliminary information on new products in production. The specifications are subject to change without notice. Verify with your local Intel Sales office that you have the latest data sheet before finalizing a design.

*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

Recommended Connections

Power and ground connections must be made to multiple V_{CC} and V_{SS} pins. Every 80C186EC-based circuit board should include separate power (V_{CC}) and ground (V_{SS}) planes. Every V_{CC} pin must be connected to the power plane, and every V_{SS} pin must be connected to the ground plane. Liberal decoupling capacitance should be placed near the processor. The processor can cause transient power surges when its output buffers transition, particularly when connected to large capacitive loads.

Low inductance capacitors and interconnects are recommended for best high frequency electrical performance. Inductance is reduced by placing the decoupling capacitors as close as possible to the processor V_{CC} and V_{SS} package pins.

Always connect any unused input to an appropriate signal level. In particular, unused interrupt inputs (NMI, INT0:7) should be connected to V_{SS} through a pull-down resistor. Leave any unused output pin unconnected.

DC SPECIFICATIONS (80C186EC/80C188EC)

Symbol	Parameter	Min	Max	Units	Notes
V _{CC}	Supply Voltage	4.5	5.5	V	
V _{IL}	Input Low Voltage	-0.5	0.3 V _{CC}	V	
V _{IH}	Input High Voltage	0.7 V _{CC}	V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage		0.45	V	$I_{OL} = 3 \text{ mA}$ (Min)
V _{OH}	Output High Voltage	V _{CC} - 0.5		V	$I_{OH} = -2 \text{ mA}$ (Min)
V _{HYR}	Input Hysteresis on RESIN	0.5		V	
I _{LI}	Input Leakage Current for Pins: AD15:0 (AD7:0, A15:8), READY, HOLD, RESIN, CLKIN, TEST/BUSY, NMI, INT7:0, T0IN, T1IN, P2.7–P2.0, P3.5–P3.0, DRQ3:0, PEREQ, ERROR		±15	μΑ	$0 \le V_{IN} \le V_{CC}$
I _{LIU}	Input Leakage for Pins with Pullups Active During Reset: A19:16, LOCK	-0.275	-5	mA	V _{IN} = 0.7 V _{CC} (Note 1)
I _{LO}	Output Leakage for Floated Output Pins		± 15	μA	0.45 \leq V _{OUT} \leq V _{CC} (Note 2)
I _{CC}	Supply Current Cold (in RESET) 80C186EC25 80C186EC20 80C186EC13		125 100 70	mA mA mA	(Notes 3, 7) (Note 3) (Note 3)
I _{ID}	Supply Current in Idle Mode 80C186EC25 80C186EC20 80C186EC13		92 76 50	mA mA mA	(Notes 4, 7) (Note 4) (Note 4)
I _{PD}	Supply Current in Powerdown Mode 80C186EC25 80C186EC20 80C186EC13		100 100 100	μΑ μΑ μΑ	(Notes 5, 7) (Note 5) (Note 5)
C _{IN}	Input Pin Capacitance	0	15	рF	$T_F = 1 MHz$
C _{OUT}	Output Pin Capacitance	0	15	pF	T _F = 1 MHz (Note 6)

NOTES:

1. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode.

2. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD.

3. Measured with the device in RESET and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

4. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

5. Measured with the device in HALT (Powerdown Mode active) and at worst case frequency, V_{CC}, and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

6. Output Capacitance is the capacitive load of a floating output pin.

7. Operating conditions for 25 MHz is 0°C to +70°C, V_{CC} = 5.0 ± 10 %.



DC SPECIFICATIONS (80L186EC13/80L188EC13)

Symbol	Parameter	Min	Max	Units	Notes
V _{CC}	Supply Voltage	2.7	5.5	V	
V _{IL}	Input Low Voltage	-0.5	0.3 V _{CC}	V	
V _{IH}	Input High Voltage	0.7 V _{CC}	$V_{CC} + 0.5$	V	
V _{OL}	Output Low Voltage		0.45	V	I _{OL} = 3 mA (Min)
V _{OH}	Output High Voltage	$V_{CC} - 0.5$		V	$I_{OH} = -2 \text{ mA}$ (Min)
V _{HYR}	Input Hysteresis on RESIN	0.5		V	
I _{LI}	Input Leakage Current for Pins: AD15:0 (AD7:0, A15:8), READY, HOLD, RESIN, CLKIN, TEST/BUSY, NMI, INT7:0, T0IN, T1IN, P2.7–P2.0, P3.5–P3.0, DRQ3:0, PEREQ, ERROR		± 15	μΑ	$0 \le V_{IN} \le V_{CC}$
I _{LIU}	Input Leakage for Pins with Pullups Active During Reset: A19:16, LOCK	-0.275	-5	mA	$V_{IN} = 0.7 V_{CC}$ (Note 1)
I _{LO}	Output Leakage for Floated Output Pins		± 15	μΑ	$\begin{array}{l} \mbox{0.45} \leq \mbox{V}_{OUT} \leq \mbox{V}_{CC} \\ \mbox{(Note 2)} \end{array}$
ICC	Supply Current Cold (in RESET) 80L186EC-13		36	mA	(Note 3)
I _{ID}	Supply Current in Idle Mode 80L186EC-13		24	mA	(Note 4)
I _{PD}	Supply Current in Powerdown Mode 80L186EC-13		30	μΑ	(Note 5)
C _{IN}	Input Pin Capacitance	0	15	pF	$T_{F} = 1 \text{ MHz}$
C _{OUT}	Output Pin Capacitance	0	15	pF	$T_F = 1 \text{ MHz}$ (Note 6)

NOTES:

1. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode.

2. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD.

3. Measured with the device in RESET and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

4. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

5. Measured with the device in HALT (Powerdown Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

6. Output Capacitance is the capacitive load of a floating output pin.

int

DC SPECIFICATIONS	(80L186EC16/80L188EC16)	(Operating Temperature 0°C to 70°C)
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Symbol	Parameter	Min	Max	Units	Notes
V _{CC}	Supply Voltage	3.0	5.5	V	
V _{IL}	Input Low Voltage	-0.5	0.3 V _{CC}	V	
V _{IH}	Input High Voltage	0.7 V _{CC}	$V_{CC} + 0.5$	V	
V _{OL}	Output Low Voltage		0.45	V	I _{OL} = 3 mA (Min)
V _{OH}	Output High Voltage	$V_{CC}-0.5$		V	$I_{OH} = -2 \text{ mA}$ (Min)
V _{HYR}	Input Hysteresis on RESIN	0.5		V	
ILI	Input Leakage Current for Pins: AD15:0 (AD7:0, A15:8), READY, HOLD, RESIN, CLKIN, TEST/BUSY, NMI, INT7:0, T0IN, T1IN, P2.7–P2.0, P3.5–P3.0, DRQ3:0, PEREQ, ERROR		± 15	μΑ	$0 \le V_{IN} \le V_{CC}$
I _{LIU}	Input Leakage for Pins with Pullups Active During Reset: A19:16, LOCK	-0.275	-5	mA	$V_{IN} = 0.7 V_{CC}$ (Note 1)
I _{LO}	Output Leakage for Floated Output Pins		± 15	μΑ	$\begin{array}{l} \mbox{0.45} \leq \mbox{V}_{OUT} \leq \mbox{V}_{CC} \\ \mbox{(Note 2)} \end{array}$
ICC	Supply Current Cold (in RESET) 80L186EC-16		45	mA	(Note 3)
I _{ID}	Supply Current in Idle Mode 80L186EC-16		35	mA	(Note 4)
I _{PD}	Supply Current in Powerdown Mode 80L186EC-16		50	μΑ	(Note 5)
C _{IN}	Input Pin Capacitance	0	15	pF	$T_F = 1 MHz$
C _{OUT}	Output Pin Capacitance	0	15	pF	T _F = 1 MHz (Note 6)

NOTES:

1. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode.

2. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD.

3. Measured with the device in RESET and at worst case frequency, V_{CC}, and temperature with ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND. 4. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL**

outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

5. Measured with the device in HALT (Powerdown Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

6. Output Capacitance is the capacitive load of a floating output pin.



I_{CC} versus Frequency and Voltage

The I_{CC} consumed by the processor is composed of two components:

- I_{PD}—The quiescent current that represents internal device leakage. Measured with all inputs at either V_{CC} or ground and no clock applied.
- 2. I_{CCS}—The switching current used to charge and discharge internal parasitic capacitance when changing logic levels. I_{CCS} is related to both the frequency of operation and the device supply voltage (V_{CC}). I_{CCS} is given by the formula:

Power = V * I = V² * C_{DEV} * f

$$\therefore I_{CCS} = V * C_{DEV} * f$$

Where:

V = Supply Voltage (V_{CC}) C_{DEV} = Device Capacitance

f = Operating Frequency

Measuring C_{PD} on a device like the 80C186EC would be difficult. Instead, C_{PD} is calculated using the above formula with I_{CC} values measured at known V_{CC} and frequency. Using the C_{PD} value, the user can calculate I_{CC} at any voltage and frequency within the specified operating range.

Example. Calculate typical I_{CC} at 14 MHz, 5.2V V_{CC}.

 $I_{CC} = I_{PD} + I_{CCS}$

- = 0.1 mA + 5.2V * 0.77 * 14 MHz
- = 56.2 mA

PDTMR Pin Delay Calculation

The PDTMR pin provides a delay between the assertion of NMI and the enabling of the internal clocks when exiting Powerdown Mode. A delay is required only when using the on chip oscillator to allow the crystal or resonator circuit to stabilize.

NOTE:

The PDTMR pin function does not apply when RESIN is asserted (i.e. a device reset while in Powerdown is similar to a cold reset and RESIN must remain active until after the oscillator has stabilized.

To calculate the value of capacitor to use to provide a desired delay, use the equation:

440 \times t = C_{PD} (5V, 25°C)

Where:

t = desired delay in **seconds** $C_{PD} =$ capacitive load on PDTMR in **microfarads**

Example. For a delay of 300 μ s, a capacitor value of $C_{PD}=440\times(300\times10^{-6}=0.132~\mu\text{F}$ is required. Round up to a standard (available) capacitor value.

NOTE:

The above equation applies to delay time longer than 10 μs and will compute the **TYPICAL** capacitance needed to achieve the desired delay. A delay variance of +50% to -25% can occur due to temperature, voltage, and device process extremes. In general, higher V_{CC} and/or lower temperatures will decrease delay time, while lower V_{CC} and/or higher temperature will increase delay time.

Parameter	Typical	Typical Max Units		Notes
CPD	0.77	1.37	mA/V*MHz	1, 2
CPD (Idle Mode)	0.55	0.96	mA/V*MHz	1, 2

NOTES:

1. Maximum C_{PD} is measured at -40° C with all outputs loaded as specified in the AC test conditions and the device in reset (or Idle Mode). Due to tester limitations, CLKOUT and OSCOUT also have 50 pF loads that increase I_{CC} by V*C*F. 2. Typical C_{PD} is calculated at 25°C assuming no loads on CLKOUT or OSCOUT and the device in reset (or Idle Mode).

AC SPECIFICATIONS

AC Characteristics—80C186EC25

Cumhal	Peremeter	25	MHz	Unite	
Symbol	Parameter	Min	Мах	Units	Notes
INPUT C	LOCK				
T _F	CLKIN Frequency	0	50	MHz	1
T _C	CLKIN Period	20	~	ns	1
T _{CH}	CLKIN High Time	8	8	ns	1, 2
T _{CL}	CLKIN Low Time	8	8	ns	1, 2
T _{CR}	CLKIN Rise Time	1	10	ns	1, 3
T _{CF}	CLKIN Fall Time	1	10	ns	1, 3
OUTPUT	CLOCK				
T _{CD}	CLKIN to CLKOUT Delay	0	17	ns	1, 4
Т	CLKOUT Period		2*T _C	ns	1
Т _{РН}	CLKOUT High Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PL}	CLKOUT Low Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PR}	CLKOUT Rise Time	1	6	ns	1, 5
T _{PF}	CLKOUT Fall Time	1	6	ns	1, 5
OUTPUT	DELAYS				
T _{CHOV1}	ALE, $\overline{S2:0}$, \overline{DEN} , DT/\overline{R} ,	3	17	ns	1, 4, 6, 7
	BHE (RFSH), LOCK, A19:16				
T _{CHOV2}	GCS0:7, LCS, UCS, NCS, RD, WR	3	20	ns	1, 4, 6, 8
T _{CLOV1}	BHE (RFSH), DEN, LOCK, RESOUT,	3	17	ns	1, 4, 6
	HLDA, T0OUT, T1OUT, A19:16				
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, AD15:0	3	20	ns	1, 4, 6
	(AD7:0, A15:8), NCS, INTA1:0, S2:0				
T _{CHOF}	RD, WR, BHE (RFSH), DT/R,	0	20	ns	1
	LOCK, S2:0, A19:16				
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	20	ns	1



AC SPECIFICATIONS

AC Characteristics—80C186EC25 (Continued)

Symbol	Parameter		25 MHz		Notes
Symbol	Farameter	Min	Max	Units	Notes
SYNCHR	ONOUS INPUTS				
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0, P2.6, P2.7	10		ns	1, 9
ТСНІН	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0	3		ns	1, 9
T _{CLIS}	AD15:0 (AD7:0), READY	10		ns	1, 10
T _{CLIH}	READY, AD15:0 (AD7:0)	3		ns	1, 10
T _{CLIS}	HOLD, PEREQ, ERROR	10		ns	1, 9
T _{CLIH}	HOLD, PEREQ, ERROR	3		ns	1, 9

NOTES:

- 1. See AC Timing Waveforms, for waveforms and definition.
- 2. Measure at V_{IH} for high time, V_{IL} for low time. 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}.
- 4. Specified for a 50 pF load, see Figure 13 for capacitive derating information.
- 5. Specified for a 50 pF load, see Figure 14 for rise and fall times outside 50 pF.
- 6. See Figure 14 for rise and fall times.
 7. T_{CHOV1} applies to <u>BHE</u> (RF<u>SH</u>), LOCK and A19:16 only after a HOLD release.
- $3. T_{CHOV2}$ applies to \overline{RD} and \overline{WR} only after a HOLD release. 9. Setup and Hold are required to guarantee recognition.
- 10. Setup and Hold are required for proper operation.

int

AC SPECIFICATIONS

AC Characteristics—80C186EC-20/80C186EC-13

Symbol	Parameter	Min	Max	Min	Мах	Unit	Notes
INPUT C	LOCK	20 MHz		13 MHz			
TF TC	CLKIN Frequency CLKIN Period	0 25	40 ∞	0 38.5	26 ∞	MHz ns	1
TCH TCL	CLKIN High Time CLKIN Low Time	10 10	80 80	12 12	80 80	ns ns	1, 2 1, 2
TCR TCF	CLKIN Rise Time CLKIN Fall Time	1	10 10	1	10 10	ns ns	1, 3 1, 3
Ουτρυτ	ГСЬОСК	1	1	1	1		
T _{CD} T T _{PH}	CLKIN to CLKOUT Delay CLKOUT Period CLKOUT High Time	0 (T/2) - 5	17 2 * TC (T/2) + 5	0 (T/2) - 5	23 2 * TC (T/2) + 5	ns ns ns	1, 4 1 1
T _{PL} T _{PR} T _{PF}	CLKOUT Low Time CLKOUT Rise Time CLKOUT Fall Time	(T/2) - 5 1 1	(T/2) + 5 6 6	(T/2) - 5 1 1	(T/2) + 5 6 6	ns ns ns	1 1, 5 1, 5
	T DELAYS				-		.,
T _{CHOV1}	ALE, <u>S2:0, DEN,</u> DT/R, BHE (RFSH), LOCK, A19:16	3	20	3	25	ns	1, 4, 6, 7
T _{CHOV2}	GCS7:0, LCS, UCS, RD, WR, NCS, WDTOUT	3	23	3	30	ns	1, 4, 6, 8
	BHE (RFSH), DEN, LOCK, RESOUT, HLDA, TOOUT, T1OUT	3	20	3	25	ns	1, 4, 6
T _{CLOV2}	RD, WR, GSC7:0, LCS, UCS, AD15:0 (AD7:0, A15:8), NCS, INTA, S2:0, A19:16	3	23	3	30	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	25	0	30	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	25	0	30	ns	1
INPUT R	EQUIREMENTS						
T _{CHIS}	TEST, NMI, T1IN, T0IN, READY, CTS1:0, BCLK1:0, P3.4, P3.5	10		10		ns	1, 9
ТСНІН	TEST, NMI, T1IN, T0IN, READY, CTS1:0, BCLK1:0, P3.4, P3.5	3		3		ns	1, 9
T _{CLIS}	AD15:0 (AD7:0), READY	10		10		ns	1, 10
T _{CLIH}	AD15:0 (AD7:0), READY	3		3		ns	1, 10
T _{CLIS}	HOLD, RESIN, PEREQ, ERROR, DRQ3:0	10		10		ns	1, 9
T _{CLIH}	HOLD, RESIN, REREQ, ERROR, DRQ3:0	3		3		ns	1, 9

NOTES:

1. See AC Timing Waveforms, for waveforms and definition.

2. Measure at VIH for high time, VIL for low time.

- 3. Only required to guarantee ICC. Maximum limits are bounded by TC, TCH and TCL.
- 4. Specified for a 50 pF load, see Figure 14 for capacitive derating information.
- 5. Specified for a 50 pF load, see Figure 15 for rise and fall times outside 50 pF.
- 5. Specified a 56 pT foot, see Figure 16 rise and fail times. 7. T_{CHOV1} applies to <u>BHE</u> (RFSH), <u>LOCK</u> and A19:16 only after a HOLD release. 8. T_{CHOV2} applies to RD and WR only after a HOLD release. 9. Setup and Hold are required to guarantee recognition.

- 10. Setup and Hold are required for proper operation.



AC Characteristics—80L186EC13

Symbol	Parameter	Min	Max	Unit	Notes
INPUT CL	оск	13 MHz			
TF	CLKIN Frequency	0	26	MHz	1
T _C	CLKIN Period	38.5	∞	ns	1
Т _{СН}	CLKIN High Time	15	~	ns	1, 2
T _{CL}	CLKIN Low Time	15	80	ns	1, 2
T _{CR}		1	10	ns	1,3
	CLKIN Fall Time	1	10	ns	1, 3
		-			
T _{CD}	CLKIN to CLKOUT Delay	0	20	ns	1, 4
T			2 * TC	ns	1
Т _{РН} т	CLKOUT High Time CLKOUT Low Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PL} T _{PR}	CLKOUT Low Time	(T/2) - 5 1	(T/2) + 5 10	ns	1, 5
T _{PF}	CLKOUT Fall Time	1	10	ns ns	1,5
		·	10	113	1, 0
	S2:0, DT/R, BHE, LOCK	3	28	ns	1, 4, 6, 7
T _{CHOV2}	LCS, UCS, DEN, A19:16, RD, WR, NCS, WDTOUT, ALE	3	32	ns	1, 4, 6, 8
Тсноуз	GCS7:0	3	34	ns	1, 4, 6
T _{CLOV1}	LOCK, RESOUT, HLDA, T0OUT, T1OUT	3	28	ns	1, 4, 6
T _{CLOV2}	RD, WR, AD15:0 (AD7:0, A15:8), BHE (RFSH), NCS, INTA, DEN	3	32	ns	1, 4, 6
T _{CLOV3}	GSC7:0, LCS, UCS	3	34	ns	1, 4, 6
T _{CLOV4}	<u>S2:0,</u> A19:16	3	37	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	30	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	35	ns	1
INPUT RE	QUIREMENTS				
T _{CHIS}	TEST, NMI, T1IN, T0IN, READY, CTS1:0, BCLK1:0, P3.4, P3.5	20		ns	1, 9
ТСНІН	TEST, NMI, T1IN, T0IN, READY, CTS1:0, BCLK1:0, P3.4, P3.5	3		ns	1, 9
T _{CLIS}	AD15:0 (AD7:0), READY	20		ns	1, 10
T _{CLIH}	AD15:0 (AD7:0), READY	3		ns	1, 10
T _{CLIS}	HOLD, RESIN, PEREQ, ERROR, DRQ3:0	20		ns	1, 9
T _{CLIH}	HOLD, RESIN, REREQ, ERROR, DRQ3:0	3		ns	1, 9

NOTES:

1. See AC Timing Waveforms, for waveforms and definition.

- 2. Measure at V_{IH} for high time, V_{IL} for low time. 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}. 4. Specified for a 50 pF load, see Figure 14 for capacitive derating information. 5. Specified for a 50 pF load, see Figure 15 for rise and fall times outside 50 pF.

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AC Characteristics—80L186EC13 (Continued)

NOTES:

6. See Figure 15 for rise and fall times.

7. T_{CHOV1} applies to BHE (RFSH), LOCK and A19:16 only after a HOLD release. 8. T_{CHOV2} applies to RD and WR only after a HOLD release.

9. Setup and Hold are required to guarantee recognition.

10. Setup and Hold are required for proper operation.

AC Characteristics—80L186EC16 (Operating Temperature 0°C to 70°C)

Symbol	Parameter	Min	Max	Unit	Notes
INPUT CL	ОСК	16 MHz			
T _F T _C T _{CH} T _{CL} T _{CR}	CLKIN Frequency CLKIN Period CLKIN High Time CLKIN Low Time CLKIN Rise Time	0 31.25 13 13 13 1	32 ∞ ∞ ∞ 10	MHz ns ns ns ns	1 1 1, 2 1, 2 1, 3
	CLKIN Fall Time	1	10	ns	1, 3
		-			
T _{CD} T T _{PH} T _{PL} T _{PR} T _{PF}	CLKIN to CLKOUT Delay CLKOUT Period CLKOUT High Time CLKOUT Low Time CLKOUT Rise Time CLKOUT Fall Time	0 (T/2) - 5 (T/2) - 5 1 1	20 2 * TC (T/2) + 5 (T/2) + 5 9 9	ns ns ns ns ns ns	1,4 1 1 1,5 1,5
Ουτρυτ Ι	DELAYS			_	
T _{CHOV1}	$\overline{S2:0}$, DT/ \overline{R} , \overline{BHE} , \overline{LOCK}	3	25	ns	1, 4, 6, 7
T _{CHOV2}	<u>ICS, UCS, DEN,</u> A19:16, RD, WR, NCS, WDTOUT, ALE	3	30	ns	1, 4, 6, 8
T _{CHOV3}	GCS7:0	3	32	ns	1, 4, 6
T _{CLOV1}	LOCK, RESOUT, HLDA, T0OUT, T1OUT	3	25	ns	1, 4, 6
T _{CLOV2}	RD, WR, AD15:0 (AD7:0, A15:8), BHE (RFSH), NCS, INTA, DEN	3	30	ns	1, 4, 6
T _{CLOV3}	GSC7:0, LCS, UCS	3	32	ns	1, 4, 6
T _{CLOV4}	<u>S2:0</u> , A19:16	3	34	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	28	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	32	ns	1
INPUT RE	QUIREMENTS				
T _{CHIS}	TEST, NMI, T1IN, T0IN, READY, CTS1:0, BCLK1:0, P3.4, P3.5	15		ns	1, 9
т _{снін}	TEST, NMI, T1IN, T0IN, READY, CTS1:0, BCLK1:0, P3.4, P3.5	3		ns	1, 9
T _{CLIS}	AD15:0 (AD7:0), READY	15		ns	1, 10
T _{CLIH}	AD15:0 (AD7:0), READY	3		ns	1, 10
T _{CLIS}	HOLD, RESIN, PEREQ, ERROR, DRQ3:0	15		ns	1, 9
T _{CLIH}	HOLD, RESIN, PEREQ, ERROR, DRQ3:0	3		ns	1, 9



AC Characteristics-80L186EC16 (Continued)

NOTES:

- 1. See AC Timing Waveforms, for waveforms and definition.
- 2. Measure at V_{IH} for high time, V_{IL} for low time.
- 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}.
- 4. Specified for a 50 pF load, see Figure 14 for capacitive derating information.
- 5. Specified for a 50 pF load, see Figure 15 for rise and fall times outside 50 pF.
- 6. See Figure 15 for rise and fall times.
- 7. T_{CHOV1} applies to \overline{BHE} (RFSH), \overline{LOCK} and A19:16 only after a HOLD release.
- 8. T_{CHOV2} applies to $\overline{\text{RD}}$ and $\overline{\text{WR}}$ only after a HOLD release.
- 9. Setup and Hold are required to guarantee recognition.
- 10. Setup and Hold are required for proper operation.

Relative Timings (80C186EC-25/20/13, 80L186EC-16/13)

Symbol	Parameter	Min	Мах	Unit	Notes				
RELATIVE TIMINGS									
T _{LHLL}	ALE Active Pulse Width	T — 15		ns					
T _{AVLL}	AD Valid Setup before ALE Falls	¹⁄₂T − 10		ns					
T _{PLLL}	Chip Select Valid before ALE Falls	¹⁄₂T − 10		ns	1				
T _{LLAX}	AD Hold after ALE Falls	¹⁄₂T − 10		ns					
T _{LLWL}	ALE Falling to WR Falling	¹⁄₂T − 15		ns	1				
T _{LLRL}	ALE Falling to RD Falling	¹⁄₂T − 15		ns	1				
T _{WHLH}	WR Rising to Next ALE Rising	¹⁄₂T − 10		ns	1				
T _{AFRL}	AD Float to RD Falling	0		ns					
T _{RLRH}	RD Active Pulse Width	2T – 5		ns	2				
T _{WLWH}	WR Active Pulse Width	2T – 5		ns	2				
T _{RHAX}	RD Rising to Next Address Active	T — 15		ns					
T _{WHDX}	Output Data Hold after WR Rising	T — 15		ns					
T _{WHPH}	WR Rise to Chip Select Rise	¹⁄₂T − 10		ns	1				
T _{RHPH}	RD Rise to Chip Select Rise	¹⁄₂T − 10		ns	1				
T _{PHPL}	Chip Select Inactive to Next Chip Select Active	¹⁄₂T − 10		ns	1				
T _{OVRH}	ONCE Active Setup to RESIN Rising	Т		ns					
T _{RHOX}	ONCE Hold after RESIN Rise	Т		ns					
T _{IHIL}	INTA High to Next INTA Low during INTA Cycle	4T - 5		ns	4				
T _{ILIH}	INTA Active Pulse Width	2T – 5		ns	2, 4				
T _{CVIL}	CAS2:0 Setup before 2nd INTA Pulse Low	8T		ns	2, 4				
T _{ILCX}	CAS2:0 Hold after 2nd INTA Pulse Low	4T		ns	2, 4				
T _{IRES}	Interrupt Resolution Time		150	ns	3				
T _{IRLH}	IR Low Time to Reset Edge Detector	50		ns					
T _{IRHIF}	IR Hold Time after 1st INTA Falling	25		ns	4, 5				

Relative Timings (80C186EC-25/20/13, 80L186EC-16/13)

NOTES:

1. Assumes equal loading on both pins.

2. Can be extended using wait states.

3. Interrupt resolution time is the delay between an unmasked interrupt request going active and the interrupt output of the 8259A module going active. This is not directly measureable by the user. For interrupt pin INT7 the delay from an active signal to an active input to the CPU would actually be twice the T_{IRES} value since the signal must pass through two 8259A modules.

4. See INTA Cycle Waveforms for definition.

5. To guarantee interrupt is not spurious.

Serial Port Mode 0 Timings (80C186EC-25/20/13, 80L186EC-16/13)

Symbol	Parameter	Min	Мах	Unit	Notes					
RELATIVE TIMINGS										
T _{XLXL}	TXD Clock Period	T (n + 1)		ns	1, 2					
T _{XLXH}	TXD Clock Low to Clock High (N \geq 1)	2T - 35	2T + 35	ns	1					
T _{XLXH}	TXD Clock Low to Clock High (N = 1)	T - 35	T + 35	ns	1					
T _{XHXL}	TXD Clock High to Clock Low (N $>$ 1)	(n - 1) T - 35	(n - 1) T + 35	ns	1, 2					
T _{XHXL}	TXD Clock High to Clock Low (N = 1)	T – 35	T + 35	ns	1					
T _{QVXH}	RXD Output Data Setup to TXD Clock High (N \geq 1)	(n – 1)T – 35		ns	1, 2					
T _{QVXH}	RXD Output Data Setup to TXD Clock High (N = 1)	T — 35		ns	1					
T _{XHQX}	RXD Output Data Hold after TXD Clock High (N \geq 1)	2T — 35		ns	1					
T _{XHQX}	RXD Output Data Hold after TXD Clock High (N = 1)	T — 35		ns	1					
T _{XHQZ}	RXD Output Data Float after Last TXD Clock High		T + 20	ns	1					
T _{DVXH}	RXD Input Data Setup to TXD Clock High	T + 20		ns	1					
T _{XHDX}	RXD Input Data Setup after TXD Clock High	0		ns	1					

NOTES:

1. See Figure 13 for Waveforms.

2. n is the value in the BxCMP register ignoring the ICLK bit.



AC TEST CONDITIONS

The AC specifications are tested with the 50 pF load shown in Figure 7. See the Derating Curves section to see how timings vary with load capacitance.

Specifications are measured at the $V_{CC}/2$ crossing point, unless otherwise specified. See AC Timing Waveforms for AC specification definitions, test pins and illustrations.

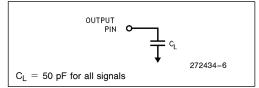


Figure 7. AC Test Load

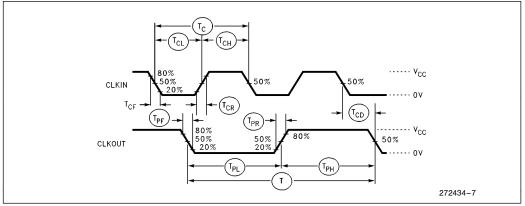


Figure 8. Input and Output Clock Waveforms

AC TIMING WAVEFORMS

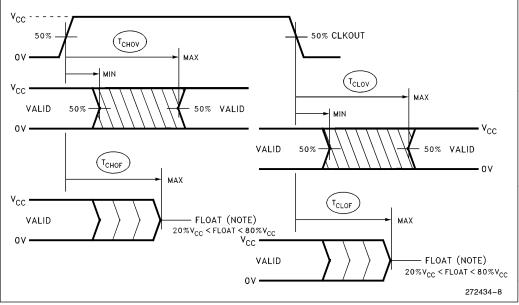


Figure 9. Output Delay and Float Waveforms

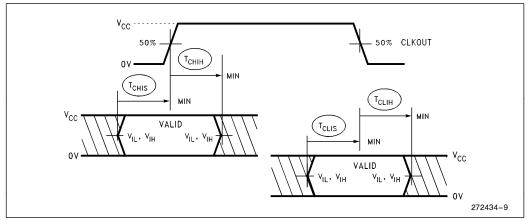


Figure 10. Input Setup and Hold

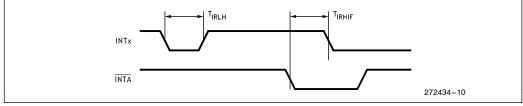


Figure 11. Relative Interrupt Signal Timings

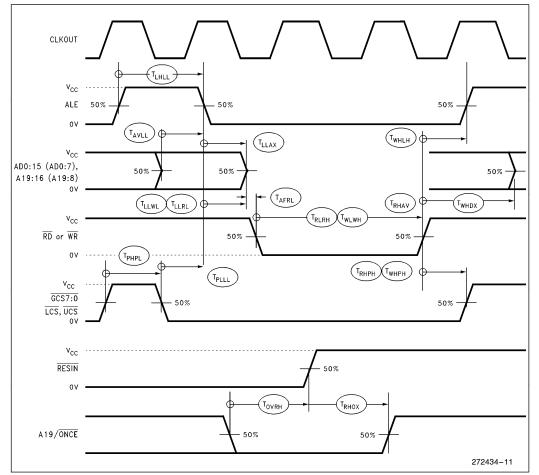


Figure 12. Relative Signal Waveform

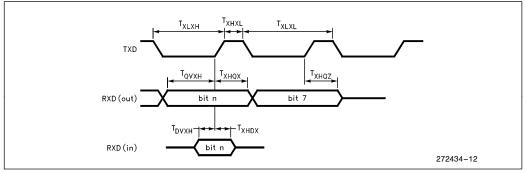


Figure 13. Serial Port Mode 0 Waveform

DERATING CURVES

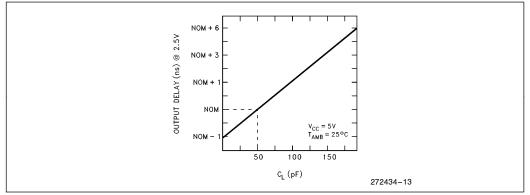


Figure 14. Typical Output Delay Variations versus Load Capacitance

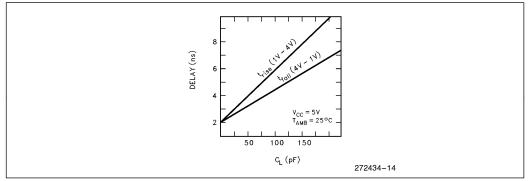


Figure 15. Typical Rise and Fall Variations versus Load Capacitance

RESET

The processor will perform a reset operation any time the $\overline{\text{RESIN}}$ pin is active. The $\overline{\text{RESIN}}$ pin is synchronized before it is presented internally, which means that the clock must be operating before a reset can take effect. From a power-on state, $\overline{\text{RESIN}}$ must be held active (low) in order to guarantee correct initialization of the processor. Failure to provide **RESIN** while the device is powering up will result in unspecified operation of the device.

Figure 16 shows the correct reset sequence when first applying power to the processor. An external clock connected to CLKIN must not exceed the V_{CC} threshold being applied to the processor. This is normally not a problem if the clock driver is supplied with the same V_{CC} that supplies the processor. When attaching a crystal to the device, RESIN must remain active until both V_{CC} and CLKOUT are stable (the length of time is application specific and depends on the startup characteristics of the crystal circuit). The RESIN pin is designed to operate cor-

rectly using a RC reset circuit, but the designer must ensure that the ramp time for V_{CC} is not so long that $\overrightarrow{\text{RESIN}}$ is never sampled at a logic low level when V_{CC} reaches minimum operating conditions.

Figure 17 shows the timing sequence when $\overline{\text{RESIN}}$ is applied after V_{CC} is stable and the device has been operating. Note that a reset will terminate all activity and return the processor to a known operating state. Any bus operation that is in progress at the time $\overline{\text{RESIN}}$ is asserted will terminate immediately (note that most control signals will be driven to their inactive state first before floating).

While RESIN is active, bus signals LOCK, A19/S16/ONCE and A18:16 are configured as inputs and weakly held high by internal pullup transistors. Only A19/ONCE can be overdriven to a low and is used to enable the ONCE Mode. Forcing LOCK or A18:16 low at any time while RESIN is low is prohibited and will cause unspecified device operation.

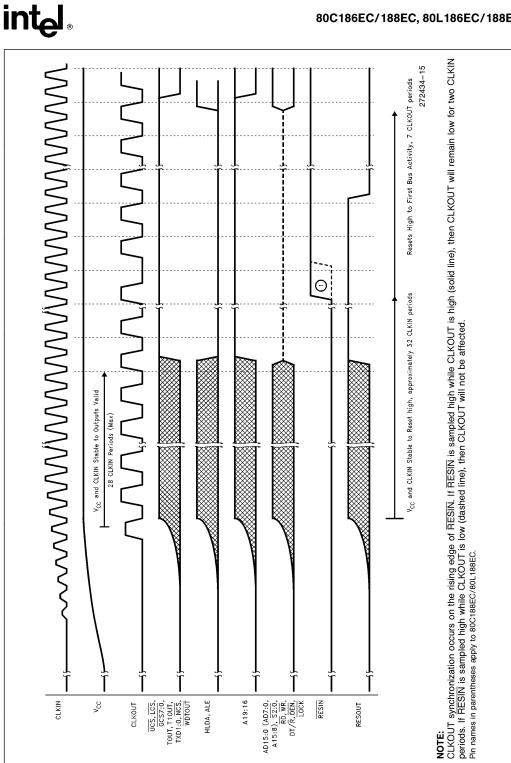


Figure 16. Cold RESET Waveforms

80C186EC/188EC, 80L186EC/188EC

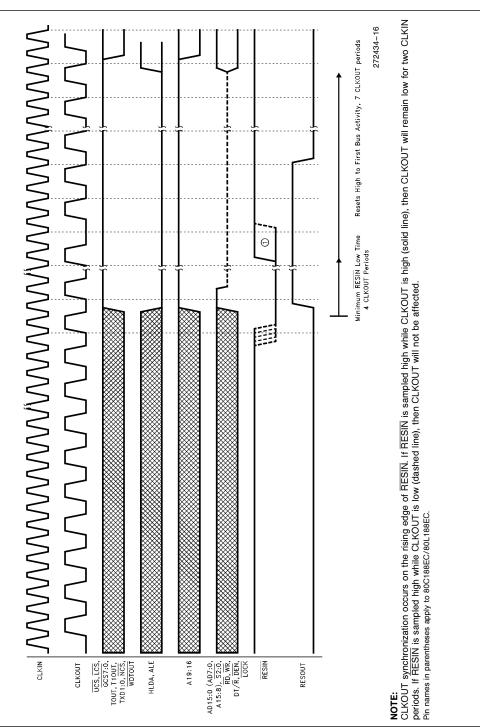


Figure 17. Warm RESET Waveforms

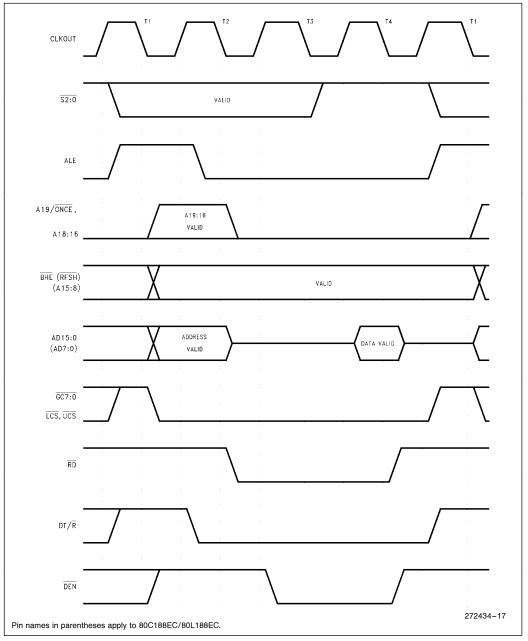
80C186EC/188EC, 80L186EC/188EC

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BUS CYCLE WAVEFORMS

Figures 18 through 24 present the various bus cycles that are generated by the processor. What is shown in the figure is the relationship of the various bus signals to CLKOUT. These figures along with the information present in AC Specifications allow the user to determine all the critical timing analysis needed for a given application.





80C186EC/188EC, 80L186EC/188EC

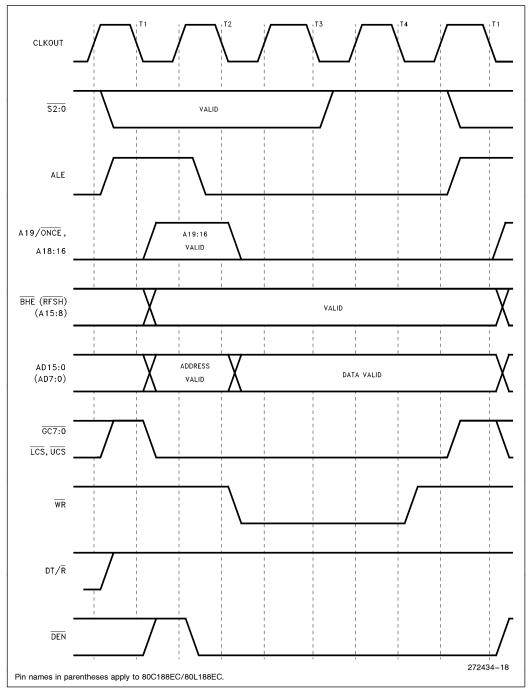
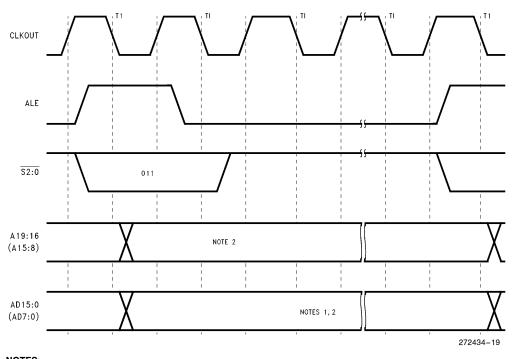


Figure 19. Memory Write and I/O Write Cycle Waveforms



NOTES:

1. Address information is invalid. If previous bus cycle was a read, then the AD15:0 (AD7:0) lines will float during T1. Otherwise, the AD15:0 (AD7:0) lines will continue to drive during T1 (data is invalid). All other control lines are in their inactive state.

2. All address lines drive zeros while in Powerdown or Idle Mode.

Pin names in parentheses apply to 80C188EC/80L188EC.

Figure 20. Halt Cycle Waveforms

80C186EC/188EC, 80L186EC/188EC

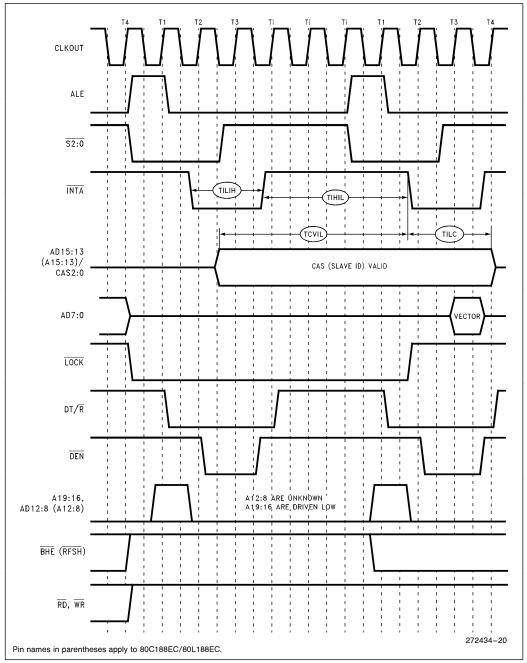
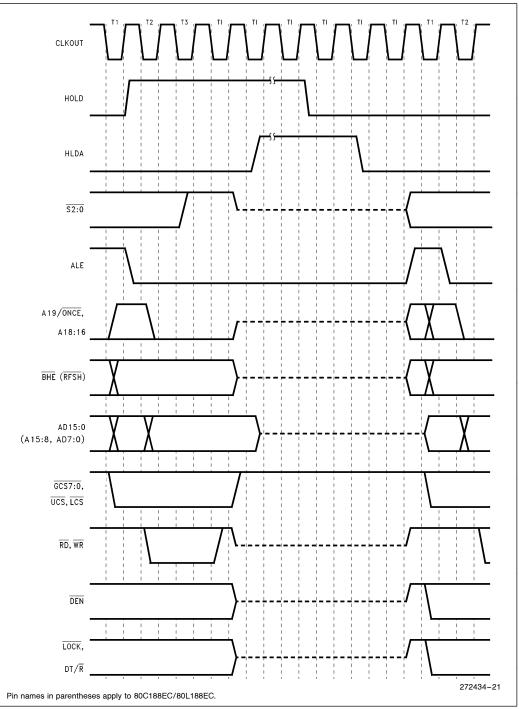


Figure 21. Interrupt Acknowledge Cycle Waveforms





80C186EC/188EC, 80L186EC/188EC

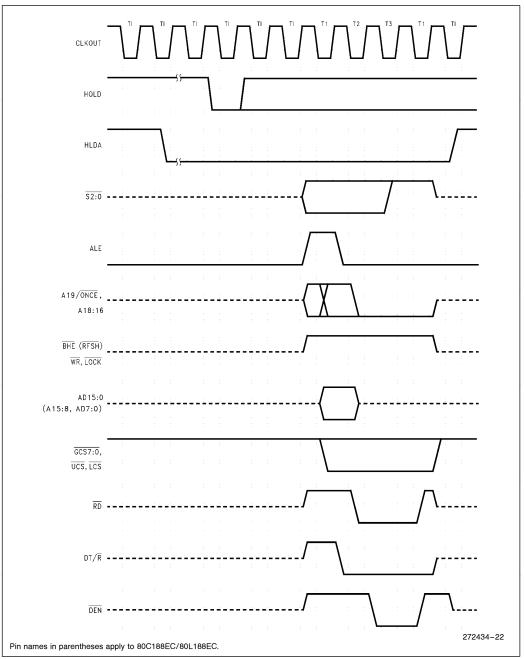


Figure 23. Refresh during HLDA Waveforms

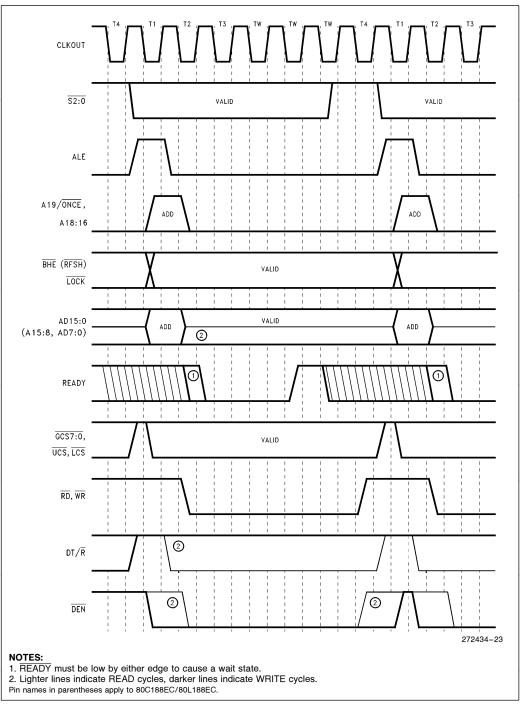


Figure 24. READY Cycle Waveforms

80C186EC/80C188EC EXECUTION TIMINGS

A determination of program execution timing must consider the bus cycles necessary to prefetch instructions as well as the number of execution unit cycles necessary to execute instructions. The following instruction timings represent the **minimum** execution time in clock cycles for each instruction. The timings given are based on the following assumptions:

- The opcode, along with any data or displacement required for execution of a particular instruction, has been prefetched and resides in the queue at the time it is needed.
- No wait states or bus HOLDs occur.
- All word-data is located on even-address boundaries (80C186EC only).

All jumps and calls include the time required to fetch the opcode of the next instruction at the destination address. All instructions which involve memory accesses can require one or two additional clocks above the minimum timings shown due to the asynchronous handshake between the bus interface unit (BIU) and execution unit.

With a 16-bit BIU, the 80C186EC has sufficient bus performance to ensure that an adequate number of prefetched bytes will reside in the queue (6 bytes) most of the time. Therefore, actual program execution time will not be substantially greater than that derived from adding the instruction timings shown.

The 80C188EC 8-bit BIU is limited in its performance relative to the execution unit. A sufficient number of prefetched bytes may not reside in the prefetch queue (4 bytes) much of the time. Therefore, actual program execution time will be substantially greater than that derived from adding the instruction timings shown.



INSTRUCTION SET SUMMARY

Function		Fo	rmat		80C186EC Clock Cycles	80C188EC Clock Cycles	Comments
DATA TRANSFER MOV = Move:							
Register to Register/Memory	1000100w	mod reg r/m			2/12	2/12*	
Register/memory to register	1000101w	mod reg r/m			2/9	2/9*	
Immediate to register/memory	1100011w	mod 000 r/m	data	data if w = 1	12/13	12/13	8/16-bit
Immediate to register	1011w reg	data	data if $w = 1$		3/4	3/4	8/16-bit
Memory to accumulator	1010000w	addr-low	addr-high		8	8*	
Accumulator to memory	1010001w	addr-low	addr-high		9	9*	
Register/memory to segment register	10001110	mod 0 reg r/m			2/9	2/13	
Segment register to register/memory	10001100	mod 0 reg r/m			2/11	2/15	
PUSH = Push:							
Memory	11111111	mod 1 1 0 r/m			16	20	
Register	01010 reg				10	14	
Segment register	0 0 0 reg 1 1 0				9	13	
Immediate	011010s0	data	data if s=0		10	14	
PUSHA = Push All	01100000				36	68	
POP = Pop:							
Memory	10001111	mod 0 0 0 r/m			20	24	
Register	01011 reg				10	14	
Segment register	0 0 0 reg 1 1 1	(reg≠01)			8	12	
POPA = Pop All	01100001				51	83	
XCHG = Exchange:							
Register/memory with register	1000011w	mod reg r/m			4/17	4/17*	
Register with accumulator	10010 reg				3	3	
IN = Input from:							
Fixed port	1110010w	port			10	10*	
Variable port	1110110w				8	8*	
OUT = Output to:							
Fixed port	1110011w	port			9	9*	
Variable port	1110111w				7	7*	
XLAT = Translate byte to AL	11010111				11	15	
LEA = Load EA to register	10001101	mod reg r/m			6	6	
LDS = Load pointer to DS	11000101	mod reg r/m	(mod≠11)		18	26	
LES = Load pointer to ES	11000100	mod reg r/m	(mod≠11)		18	26	
LAHF = Load AH with flags	10011111				2	2	
SAHF = Store AH into flags	10011110				3	3	
PUSHF = Push flags	10011100				9	13	
POPF = Pop flags	10011101				8	12	
Chadad aroan indicato instructi	•						

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

INSTRUCTION SET SUMMARY (Continued)

Function		Fo	rmat		80C186EC Clock Cycles	80C188EC Clock Cycles	Comments
DATA TRANSFER (Continued) SEGMENT = Segment Override:							
cs	00101110				2	2	
SS	00110110				2	2	
DS	00111110				2	2	
ES	00100110				2	2	
ARITHMETIC ADD = Add:	L	1					
Reg/memory with register to either	0 0 0 0 0 0 d w	mod reg r/m			3/10	3/10*	
Immediate to register/memory	100000sw	mod 0 0 0 r/m	data	data if s w=01	4/16	4/16*	
Immediate to accumulator	0000010w	data	data if $w = 1$]	3/4	3/4	8/16-bit
ADC = Add with carry:							
Reg/memory with register to either	0 0 0 1 0 0 d w	mod reg r/m			3/10	3/10*	
Immediate to register/memory	100000sw	mod 0 1 0 r/m	data	data if s w=01	4/16	4/16*	
Immediate to accumulator	0001010w	data	data if $w = 1$]	3/4	3/4	8/16-bit
INC = Increment:							
Register/memory	1111111w	mod 0 0 0 r/m			3/15	3/15*	
Register	01000 reg				3	3	
SUB = Subtract:							
Reg/memory and register to either	001010dw	mod reg r/m			3/10	3/10*	
Immediate from register/memory	10000sw	mod 1 0 1 r/m	data	data if s w=01	4/16	4/16*	
Immediate from accumulator	0010110w	data	data if $w = 1$	J	3/4	3/4*	8/16-bit
SBB = Subtract with borrow:							
Reg/memory and register to either	000110dw	mod reg r/m			3/10	3/10*	
Immediate from register/memory	100000sw	mod 0 1 1 r/m	data	data if s w=01	4/16	4/16*	
Immediate from accumulator	0001110w	data	data if $w = 1$		3/4	3/4*	8/16-bit
DEC = Decrement		1004 (0/15	0/15*	
Register/memory	1111111w	mod 0 0 1 r/m			3/15	3/15*	
Register	01001 reg				3	3	
CMP = Compare:	0011101w	mod rog r/m			3/10	3/10*	
Register/memory with register		mod reg r/m					
Register with register/memory	0011100w	mod reg r/m			3/10	3/10*	
Immediate with register/memory	100000sw	mod 1 1 1 r/m	data	data if s w=01	3/10	3/10*	0/10/1
Immediate with accumulator	0011110w	data	data if w = 1	J	3/4	3/4	8/16-bit
NEG = Change sign register/memory	1111011w	mod 0 1 1 r/m			3/10	3/10*	
AAA = ASCII adjust for add	00110111				8	8	
DAA = Decimal adjust for add	00100111				4	4	
AAS = ASCII adjust for subtract	00111111				7	7	
DAS = Decimal adjust for subtract	00101111				4	4	
MUL = Multiply (unsigned):	1111011w	mod 100 r/m					
Register-Byte Register-Word Memory-Byte Memory-Word					26–28 35–37 32–34 41–43	26-28 35-37 32-34 41-43*	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:



INSTRUCTION SET SUMMARY (Continued)

Function		Fo	rmat		80C186EC Clock Cycles	80C188EC Clock Cycles	Comments
ARITHMETIC (Continued)							
IMUL = Integer multiply (signed):	1111011w	mod 1 0 1 r/m					
Register-Byte Register-Word					25-28 34-37	25-28 34-37	
Memory-Byte					31-34	34-37	
Memory-Word	_				40-43	40-43*	
IMUL = Integer Immediate multiply (signed)	011010s1	mod reg r/m	data	data if s=0	22–25/ 29–32	22-25/ 29-32	
DIV = Divide (unsigned):	1111011w	mod 1 1 0 r/m					
Register-Byte					29	29	
Register-Word Memory-Byte					38 35	38 35	
Memory-Word					44	44*	
IDIV = Integer divide (signed):	1111011w	mod 1 1 1 r/m					
Register-Byte					44-52	44-52	
Register-Word Memory-Byte					53-61 50-58	53-61 50-58	
Memory-Word					59-67	59-67*	
AAM = ASCII adjust for multiply	11010100	00001010			19	19	
AAD = ASCII adjust for divide	11010101	00001010			15	15	
CBW = Convert byte to word	10011000]			2	2	
CWD = Convert word to double word	10011001]			4	4	
LOGIC Shift/Rotate Instructions:							
Register/Memory by 1	1101000w	mod TTT r/m			2/15	2/15	
Register/Memory by CL	1101001w	mod TTT r/m			5+n/17+n	5+n/17+n	
Register/Memory by Count	1100000w	mod TTT r/m	count		5+n/17+n	5+n/17+n	
AND = And:		TTT Instruction 0 0 0 ROL 0 0 1 ROR 0 1 0 RCL 0 1 1 RCR 1 0 0 SHL/SAL 1 0 1 SHR 1 1 1 SAR					
Reg/memory and register to either	001000dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	1000000w	mod 1 0 0 r/m	data	data if w = 1	4/16	4/16*	
Immediate to accumulator	0010010w	data	data if w=1		3/4	3/4*	8/16-bit
TEST = And function to flags, no resu	lt:						
Register/memory and register	1000010w	mod reg r/m			3/10	3/10	
Immediate data and register/memory	1111011w	mod 0 0 0 r/m	data	data if w = 1	4/10	4/10*	
Immediate data and accumulator	1010100w	data	data if w=1		3/4	3/4	8/16-bit
OR=Or:							
Reg/memory and register to either	000010dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	100000w	mod 0 0 1 r/m	data	data if w = 1	4/16	4/16*	
Immediate to accumulator	0000110w	data	data if w = 1		3/4	3/4*	8/16-bit

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

INSTRUCTION SET SUMMARY (Continued)

Function		Fo	rmat		80C186EC Clock Cycles	80C188EC Clock Cycles	Comments
LOGIC (Continued) XOR = Exclusive or:							
Reg/memory and register to either	001100dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	1000000w	mod 1 1 0 r/m	data	data if w = 1	4/16	4/16*	
Immediate to accumulator	0011010w	data	data if w = 1		3/4	3/4	8/16-bit
NOT = Invert register/memory	1111011w	mod 0 1 0 r/m		I	3/10	3/10*	
STRING MANIPULATION		mod o r o n/m			0,10	0,10	
MOVS = Move byte/word	1010010w]			14	14*	
CMPS = Compare byte/word	1010011w]			22	22*	
SCAS = Scan byte/word	1010111w				15	15*	
LODS = Load byte/wd to AL/AX	1010110w				12	12*	
STOS = Store byte/wd from AL/AX	1010101w				10	10*	
INS = Input byte/wd from DX port	0110110w				14	14	
OUTS = Output byte/wd to DX port	0110111w				14	14	
Repeated by count in CX (REP/REPE/R	EPZ/REPNE/REPN	IZ)					
MOVS = Move string	11110010	1010010w			8+8n	8+8n*	
CMPS = Compare string	1111001z	1010011w			5+22n	5+22n*	
SCAS = Scan string	1111001z	1010111w			5+15n	5+15n*	
LODS = Load string	11110010	1010110w			6+11n	6+11n*	
STOS = Store string	11110010	1010101w			6+9n	6+9n*	
INS = Input string	11110010	0110110w			8+8n	8+8n*	
OUTS = Output string	11110010	0110111w			8+8n	8+8n*	
CONTROL TRANSFER							
CALL = Call:							
Direct within segment	11101000	disp-low	disp-high		15	19	
Register/memory indirect within segment	11111111	mod 0 1 0 r/m			13/19	17/27	
				1			
Direct intersegment	10011010	segmer			23	31	
		segment	selector				
Indirect intersegment	11111111	mod 0 1 1 r/m	(mod \neq 11)		38	54	
JMP = Unconditional jump:							
Short/long	11101011	disp-low			14	14	
Direct within segment	11101001	disp-low	disp-high		14	14	
Register/memory indirect within segment	11111111	mod 1 0 0 r/m			11/17	11/21	
Direct intersegment	11101010		nt offset		14	14	
		segment	selector				
Indirect intersegment	11111111	mod 1 0 1 r/m	(mod \neq 11)		26	34	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

INSTRUCTION SET SUMMARY (Continued)

Function		Format			80C186EC Clock Cycles	80C188EC Clock Cycles	Comments
CONTROL TRANSFER (Continued) RET = Return from CALL:							
Within segment	11000011				16	20	
Within seg adding immed to SP	11000010	data-low	data-high]	18	22	
Intersegment	11001011				22	30	
Intersegment adding immediate to SP	11001010	data-low	data-high]	25	33	
JE/JZ = Jump on equal/zero	01110100	disp			4/13	4/13	JMP not
JL/JNGE = Jump on less/not greater or equal	01111100	disp			4/13	4/13	taken/JMP taken
JLE/JNG = Jump on less or equal/not greater	01111110	disp			4/13	4/13	takon
JB/JNAE = Jump on below/not above or equal	01110010	disp			4/13	4/13	
JBE/JNA = Jump on below or equal/not above	01110110	disp			4/13	4/13	
JP/JPE = Jump on parity/parity even	01111010	disp			4/13	4/13	
JO = Jump on overflow	01110000	disp			4/13	4/13	
JS = Jump on sign	01111000	disp			4/13	4/13	
JNE/JNZ = Jump on not equal/not zero	01110101	disp			4/13	4/13	
JNL/JGE = Jump on not less/greater or equal	01111101	disp			4/13	4/13	
JNLE/JG = Jump on not less or equal/greater	01111111	disp			4/13	4/13	
JNB/JAE = Jump on not below/above or equal	01110011	disp			4/13	4/13	
JNBE/JA = Jump on not below or equal/above	01110111	disp			4/13	4/13	
JNP/JPO = Jump on not par/par odd	01111011	disp			4/13	4/13	
JNO = Jump on not overflow	01110001	disp			4/13	4/13	
JNS = Jump on not sign	01111001	disp			4/13	4/13	
JCXZ = Jump on CX zero	11100011	disp			5/15	5/15	
LOOP = Loop CX times	11100010	disp			6/16	6/16	LOOP not
LOOPZ/LOOPE = Loop while zero/equal	11100001	disp			6/16	6/16	taken/LOOP taken
LOOPNZ/LOOPNE = Loop while not zero/equal	11100000	disp			6/16	6/16	anon
ENTER = Enter Procedure L = 0 L = 1 L > 1	11001000	data-low	data-high	L		19 29 26+20(n-1)	
LEAVE = Leave Procedure	11001001				8	8	
INT = Interrupt: Type specified	11001101	type			47	47	
Type 3	11001100	type			47	47	if INT. taken/
INTO = Interrupt on overflow	11001110				48/4	48/4	if INT. not taken
IRET = Interrupt return	11001111				28	28	
BOUND = Detect value out of range	01100010	mod reg r/m			33-35	33-35	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

INSTRUCTION SET SUMMARY (Continued)

Function	Format	80C186EC Clock Cycles	80C188EC Clock Cycles	Comments
PROCESSOR CONTROL				
CLC = Clear carry	1111000	2	2	
CMC = Complement carry	11110101	2	2	
STC = Set carry	1111001	2	2	
CLD = Clear direction	1111100	2	2	
STD = Set direction	1111101	2	2	
CLI = Clear interrupt	1111010	2	2	
STI = Set interrupt	1111011	2	2	
HLT = Halt	11110100	2	2	
WAIT = Wait	10011011	6	6	$\text{if }\overline{TEST}=0$
LOCK = Bus lock prefix	11110000	2	2	
NOP = No Operation	1001000	3	3	
	(TTT LLL are opcode to processor extension)			

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

*Clock cycles shown for byte transfers, for word operations, add 4 clock cycles for all memory transfers.

	tive Address (EA) of the memory operand ed according to the mod and r/m fields:
if mod =	11 then r/m is treated as a REG field
if mod =	00 then DISP = 0^* , disp-low and disp-
	high are absent
if mod =	01 then DISP = disp-low sign-extended
	to 16-bits, disp-high is absent
if mod =	10 then $DISP = disp-high$: disp-low
if r/m =	000 then $EA = (BX) + (SI) + DISP$
if r/m =	001 then $EA = (BX) + (DI) + DISP$
if r/m =	010 then $EA = (BP) + (SI) + DISP$
ifr/m =	011 then $FA = (BP) + (DI) + DISP$

- if r/m = 011 then EA = (BP) + (DI) + DISF if r/m = 100 then EA = (SI) + DISP
- if r/m = 100 then EA = (SI) + DISPif r/m = 101 then EA = (DI) + DISP
- if r/m = 101 then EA = (DI) + DISP*
- if r/m = 111 then EA = (BX) + DISP

DISP follows 2nd byte of instruction (before data if required)

*except if mod = 00 and r/m = 110 then EA = disp-high: disp-low.

EA calculation time is 4 clock cycles for all modes, and is included in the execution times given whenever appropriate.

Segment Override Prefix

0	0	1	reg	1	1	0
---	---	---	-----	---	---	---

reg is assigned according to the following:

	Segmen			
reg	Register			
00	ES			
01	CS			
10	SS			
11	DS			

REG is assigned according to the following table:

16-Bit (w = 1)	8-Bit (w = 0)
000 AX	000 AL
001 CX	001 CL
010 DX	010 DL
011 BX	011 BL
100 SP	100 AH
101 BP	101 CH
110 SI	110 DH
111 DI	111 BH

The physical addresses of all operands addressed by the BP register are computed using the SS segment register. The physical addresses of the destination operands of the string primitive operations (those addressed by the DI register) are computed using the ES segment, which may not be overridden.



ERRATA

An 80C186EC/80L186EC with a STEPID value of 0002H has no known errata. A device with a STEPID of 0002H can be visually identified by noting the **presence** of an "A" or "B" alpha character next to the FPO number or the absence of any alpha character. The FPO number location is shown in Figures 4, 5 and 6.

REVISION HISTORY

This data sheet replaces the following data sheets:

272076-003 80C188EC 272332-001 80L186EC 272333-001 80L188EC 272373-001 SB80C188EC/SB80L188EC 272372-001 SB80C186EC/SB80L186EC	272072-003	80C186EC
272333-001 80L188EC 272373-001 SB80C188EC/SB80L188EC	272076-003	80C188EC
272373-001 SB80C188EC/SB80L188EC	272332-001	80L186EC
	272333-001	80L188EC
272372-001 SB80C186EC/SB80L186EC	272373-001	SB80C188EC/SB80L188EC
	272372-001	SB80C186EC/SB80L186EC